



Thèse de doctorat

Soutenue publiquement le 26 novembre 2010

# Etude de la conduction électrique dans les diélectriques à forte permittivité utilisés en microélectronique

Jean Coignus

Directeur de thèse :

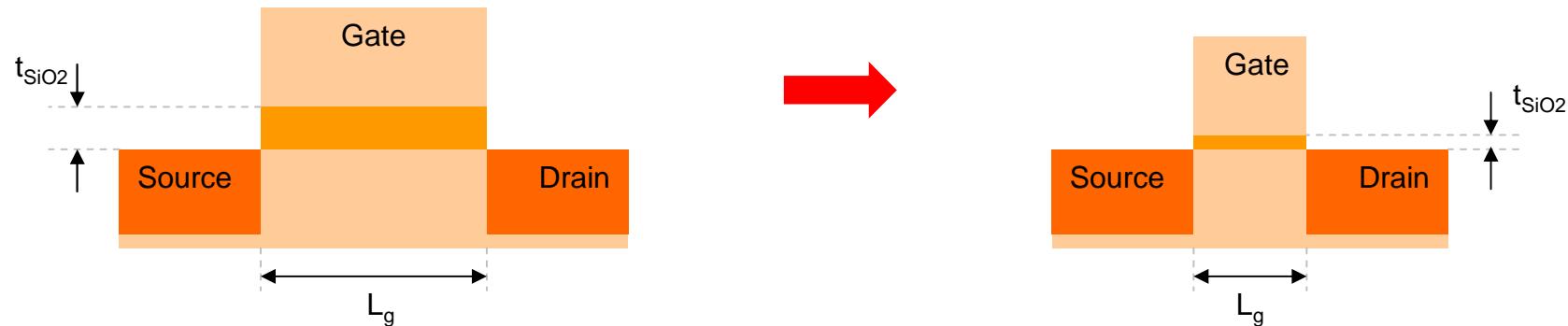
M. Raphaël CLERC  
IMEP-LAHC

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CEA-LETI Minatec

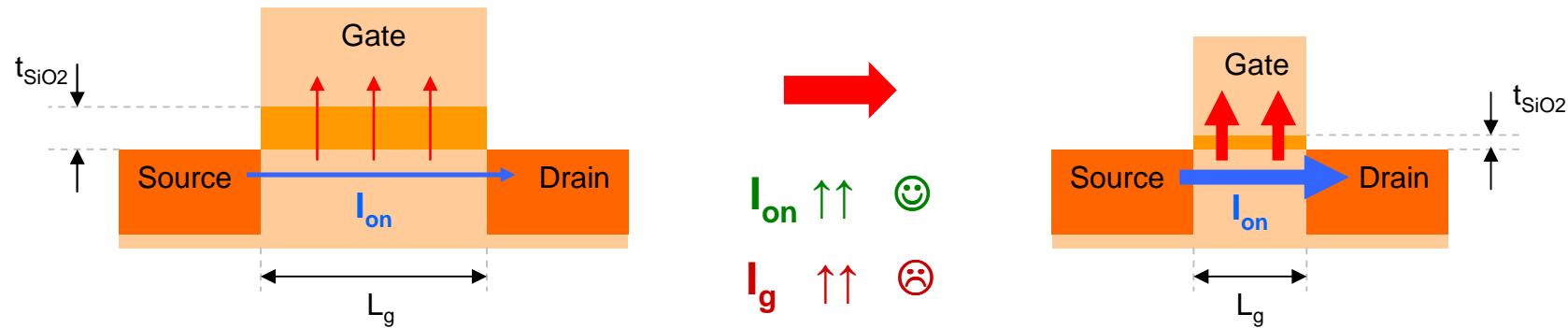
# Fundamental limits of $\text{SiO}_2$ thickness downscaling

- Conventional bulk MOSFET scaling



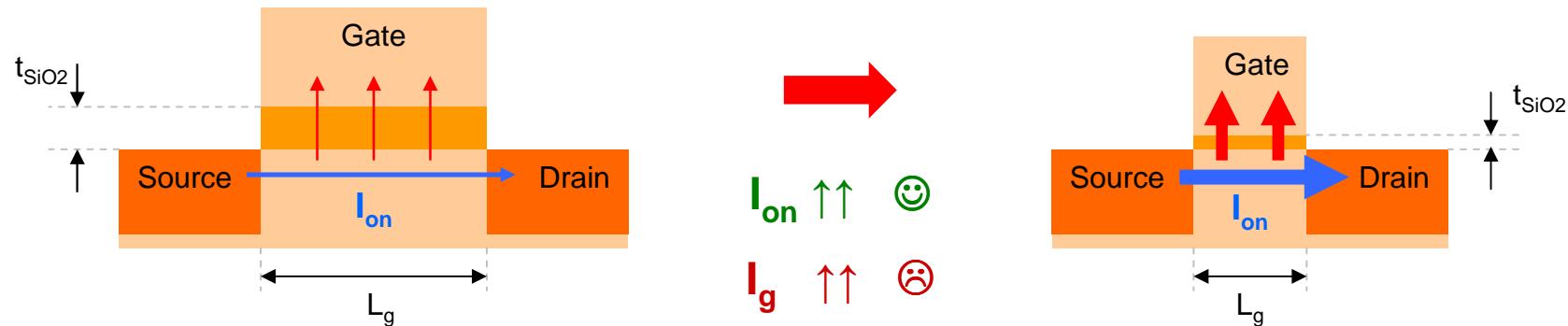
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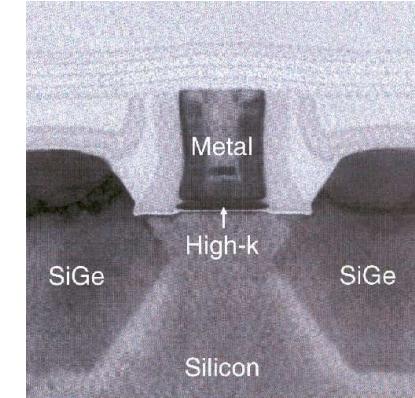


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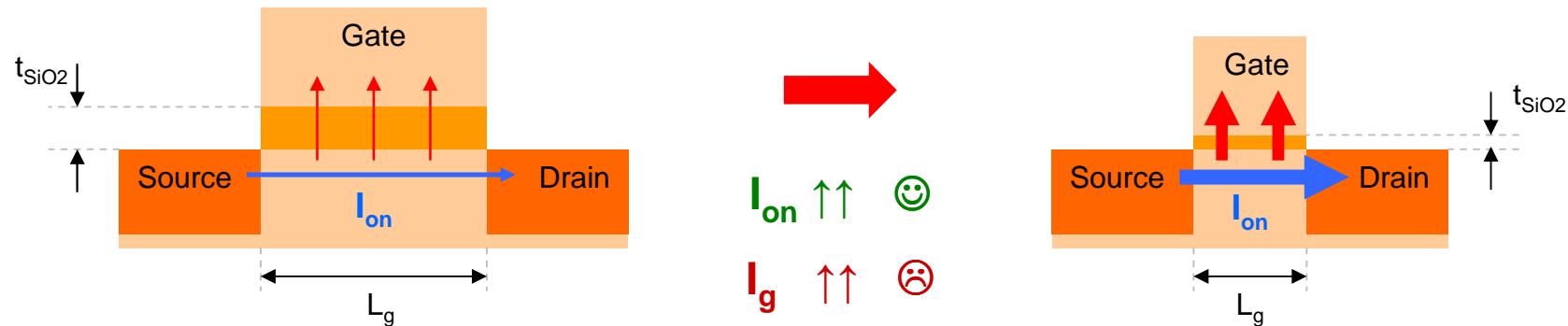
- High- $\kappa$  dielectrics : mandatory for HP 45nm node and beyond



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# Fundamental limits of $\text{SiO}_2$ thickness downscaling

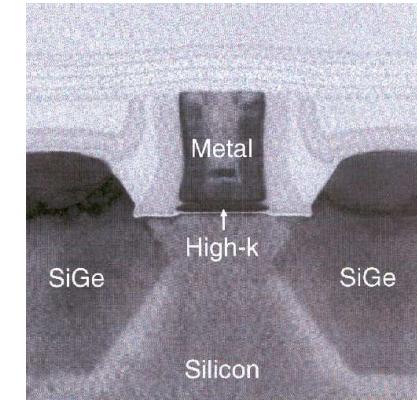
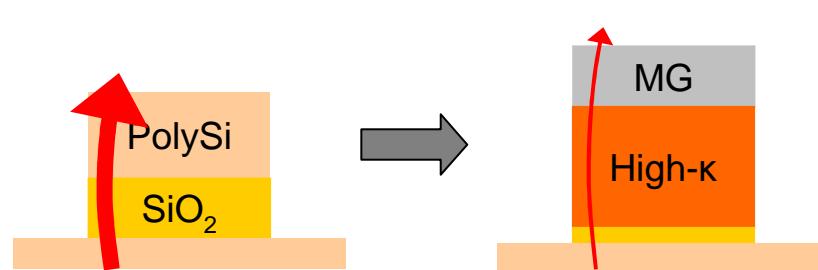
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- High-k dielectrics : mandatory for HP 45nm node and beyond

**Basics :**

**higher permittivity = higher  $t_{\text{phys}}$  @constant  $C_{\text{ox}}$**



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# High- $\kappa$ dielectrics integration

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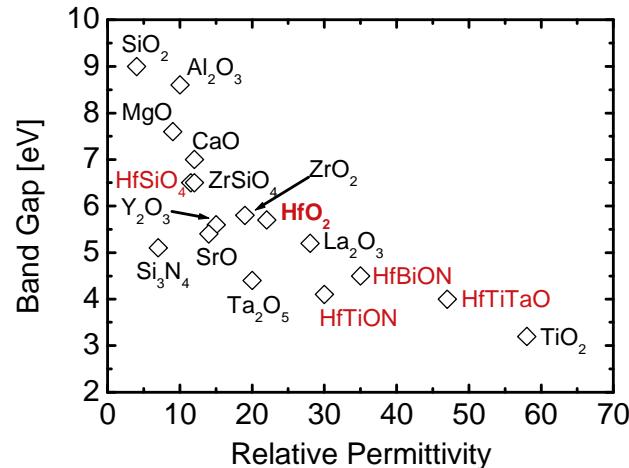
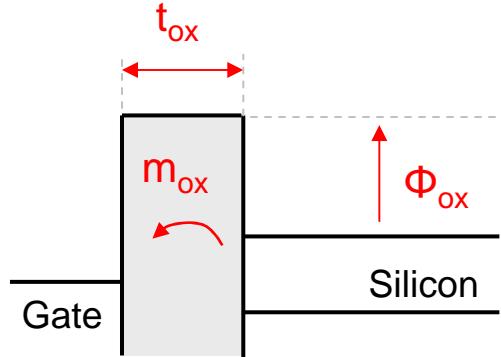
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# High- $\kappa$ dielectrics integration

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- **Dielectric parameters**

$I_g$  strongly correlated to  $m / \Phi$  : high- $\kappa$  dielectrics appear more conductive



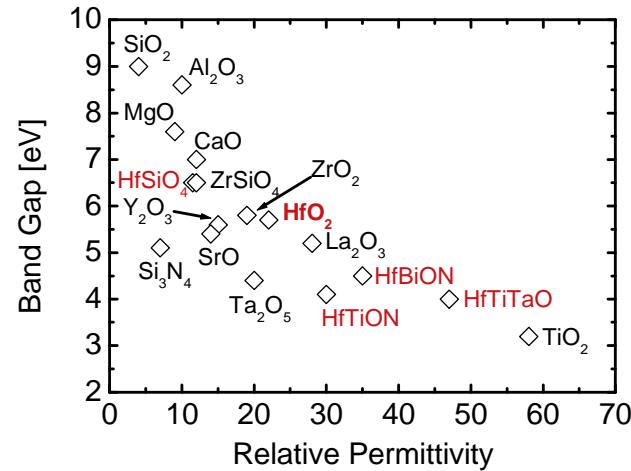
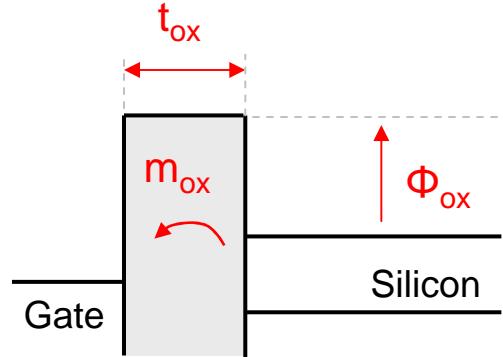
Huang VLSI '09

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- Transport mechanisms

SiO<sub>2</sub> → Direct Tunneling

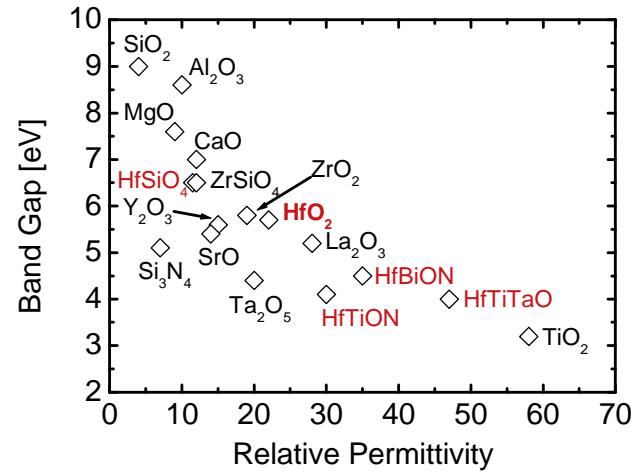
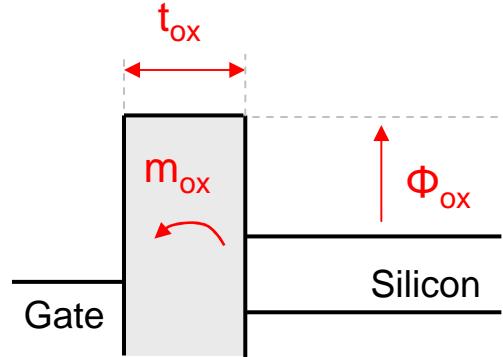
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- **Transport mechanisms**

SiO<sub>2</sub> → Direct Tunneling

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- **Integration limitations (HfO<sub>2</sub> case) : presence of an Interfacial Layer**

# State of the art

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- Gate leakage current modeling has already been studied

[Lo EDL '97, Li TED '06, Palestri TED '07...]

# State of the art

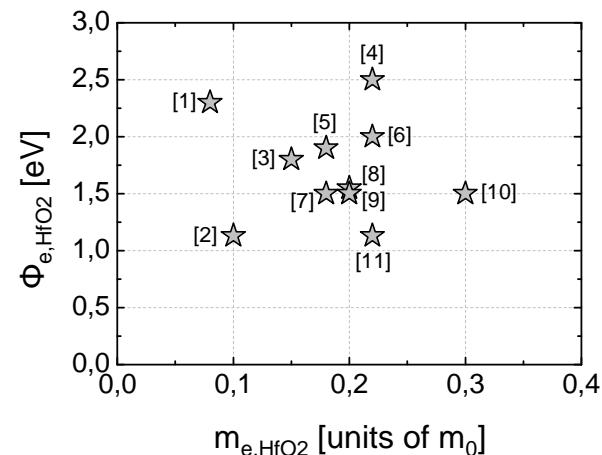
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[Lo EDL '97, Li TED '06, Palestri TED '07...]
- However, this topic remains controversial
  - $I_g$  @300K
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[Hou EDL '03, Govoreanu SSE '04]
    - Additional transport mechanisms ?  
[Xu APL 2002, Blank JAP 2005, Houssa JAP 2000]
  - Interfacial Layer may differ from pure  $\text{SiO}_2$   
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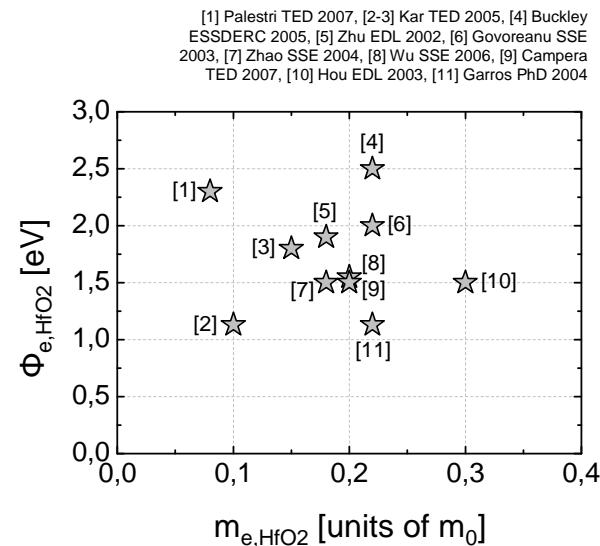
[1] Palestri TED 2007, [2-3] Kar TED 2005, [4] Buckley ESSDERC 2005, [5] Zhu EDL 2002, [6] Govoreanu SSE 2003, [7] Zhao SSE 2004, [8] Wu SSE 2006, [9] Campera TED 2007, [10] Hou EDL 2003, [11] Garros PhD 2004



➔ Lack of complete experimental studies

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## Aim of this work :

Re-investigate transport mechanisms in high- $\kappa$  gate stacks by mean of a complete experimental study performed :  
- at low temperature (transport mechanisms)  
- on various HKGS showing thickness variants (IL nature investigation, EMA validity)

# Outline

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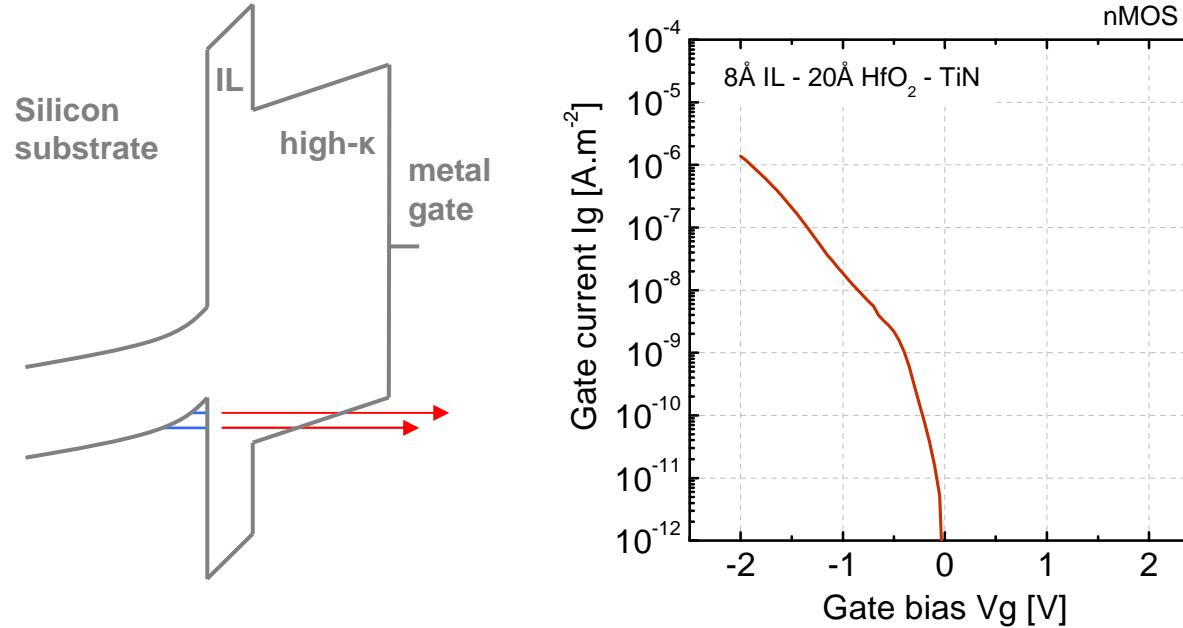
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  - Self-consistent Poisson-Schrödinger simulation
  - Transmission probability
- **Experimental investigation of leakage current in  $\text{HfO}_2$  gate stacks**
  - Transport mechanisms
  - Dielectric thicknesses extraction
  - Tunneling parameters extraction
  - Dipole effect in Mg-capped  $\text{HfO}_2$  gate stacks
- **Conclusions**

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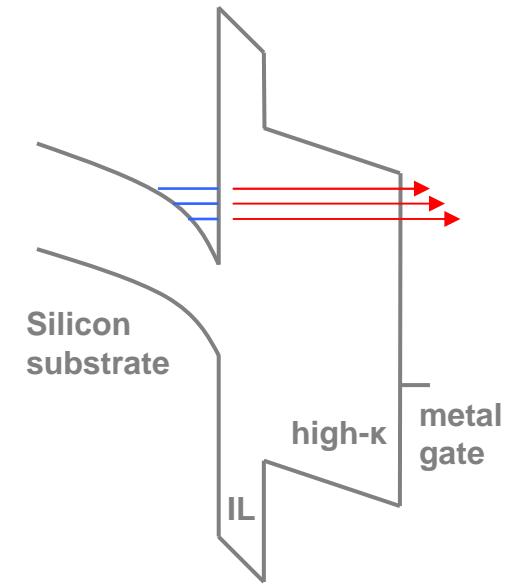
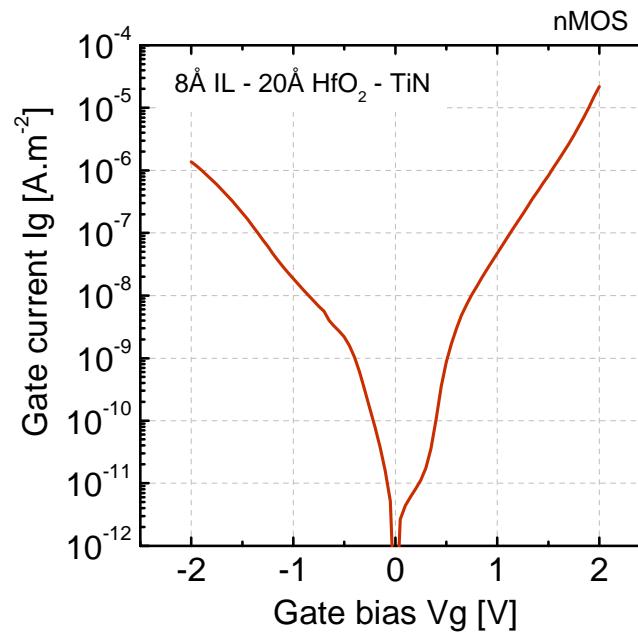
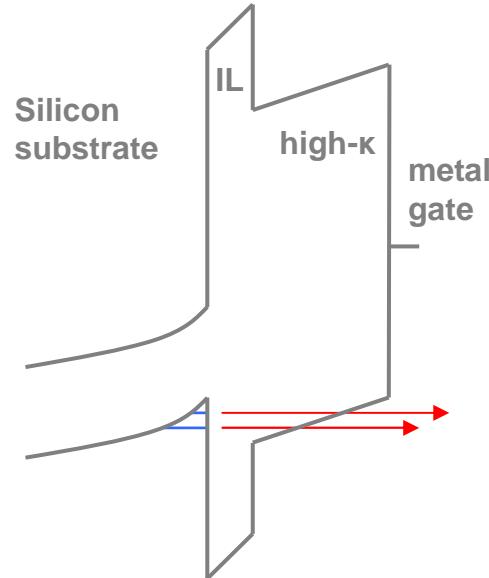
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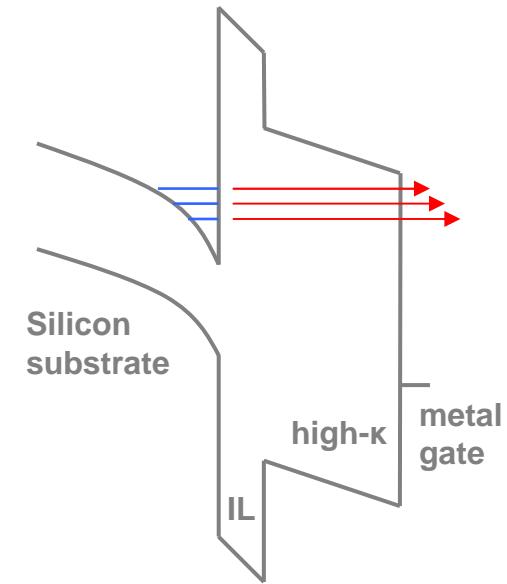
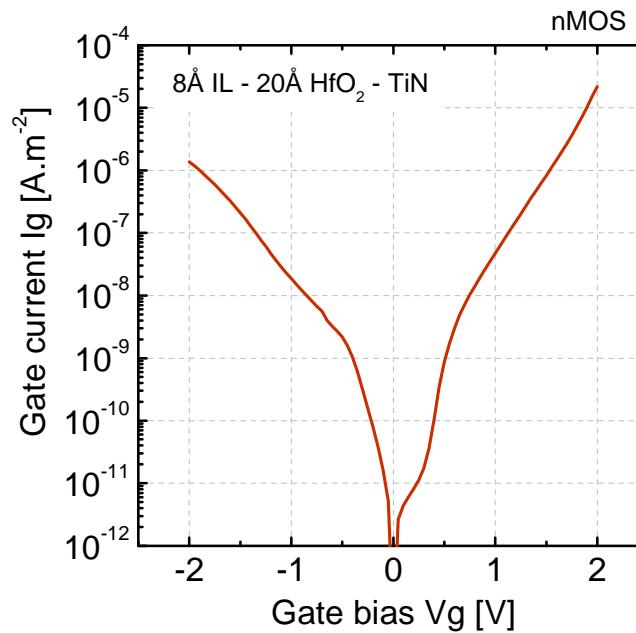
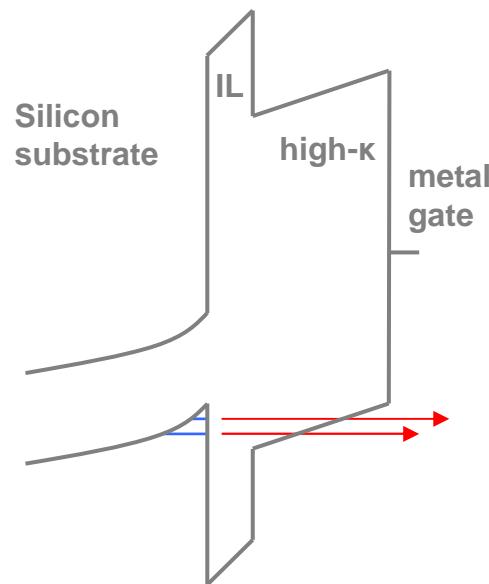
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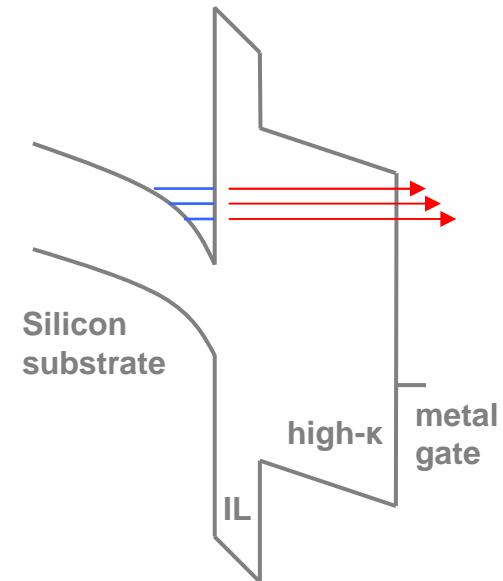
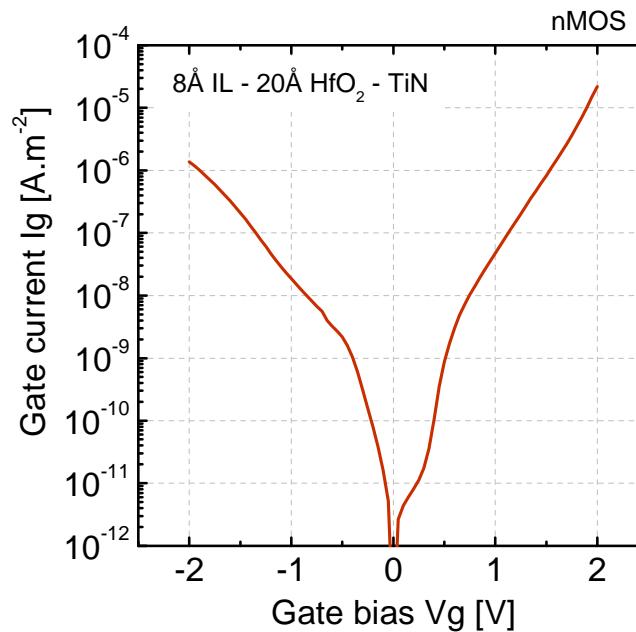
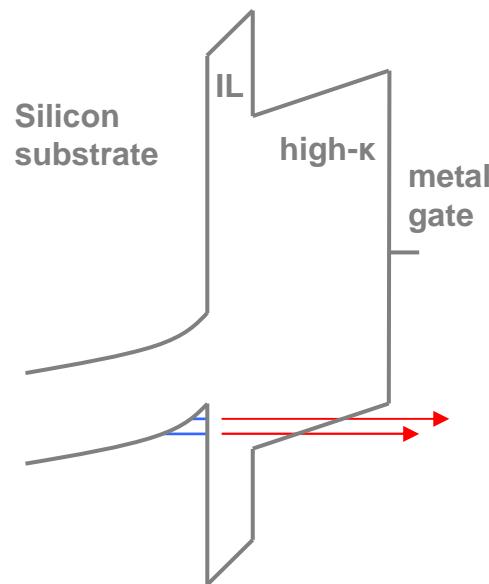


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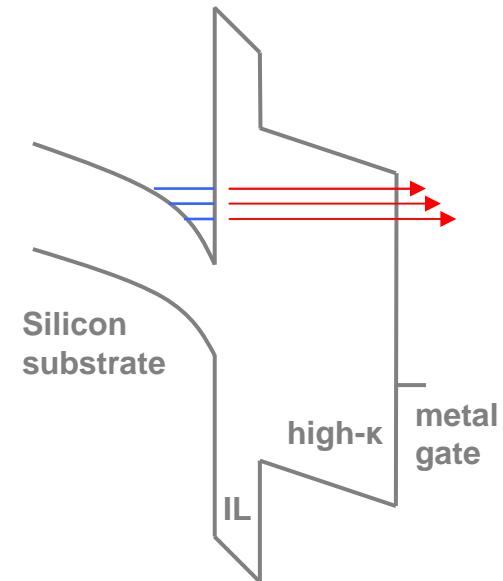
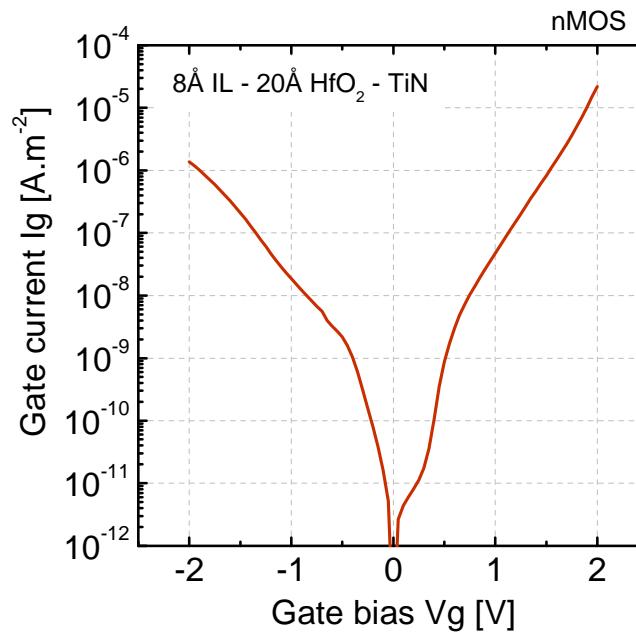
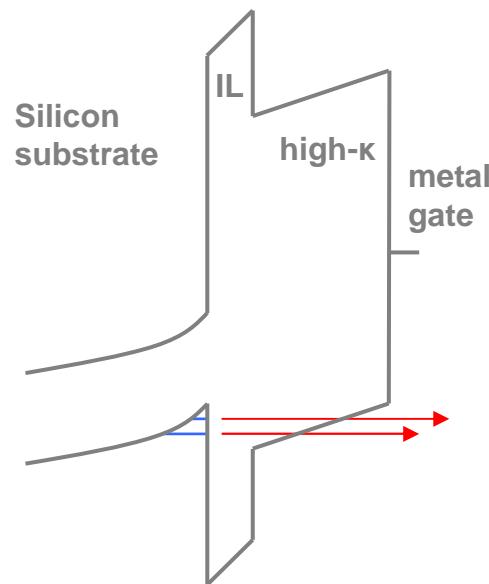
- Tunneling current from 2D gas : 
$$I_g = \sum_i Q_i(E_i) \cdot f_i(E_i) \cdot T_i(E_i)$$

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$$I_g = \sum_i Q_i(E_i) \cdot f_i(E_i) \cdot T_i(E_i)$$
- 1.  $Q_i(V_g)$  and  $E_i(V_g)$  : Poisson-Schrödinger simulation

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- Tunneling current from 2D gas :  $I_g = \sum_i Q_i(E_i) \cdot f_i(E_i) \cdot T_i(E_i)$
- 1.  $Q_i(V_g)$  and  $E_i(V_g)$  : Poisson-Schrödinger simulation  
2.  $T_i(E_i)$  : transmission probability modeling  
 $= \text{fct} ( m_{IL} / \Phi_{IL} / m_{high-k} / \Phi_{high-k} )$

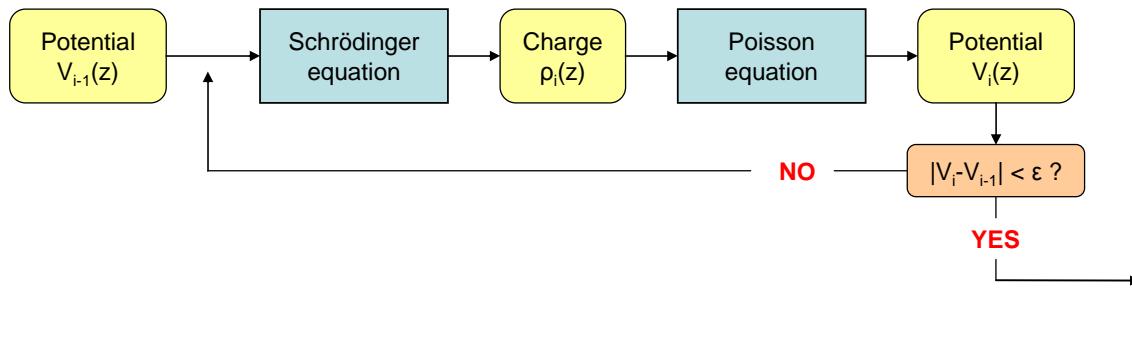
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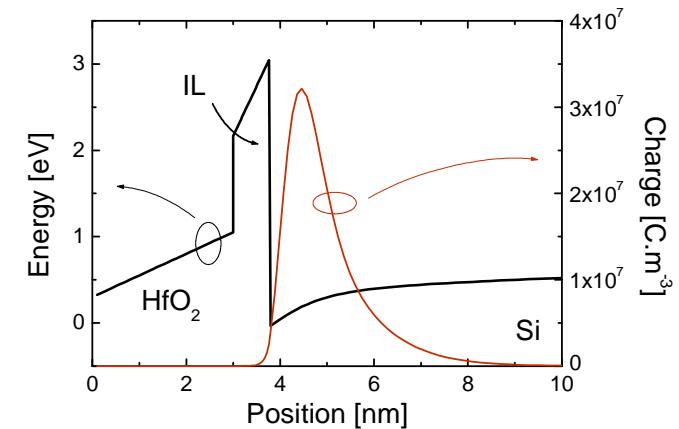
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# Poisson-Schrödinger simulation

- Principle

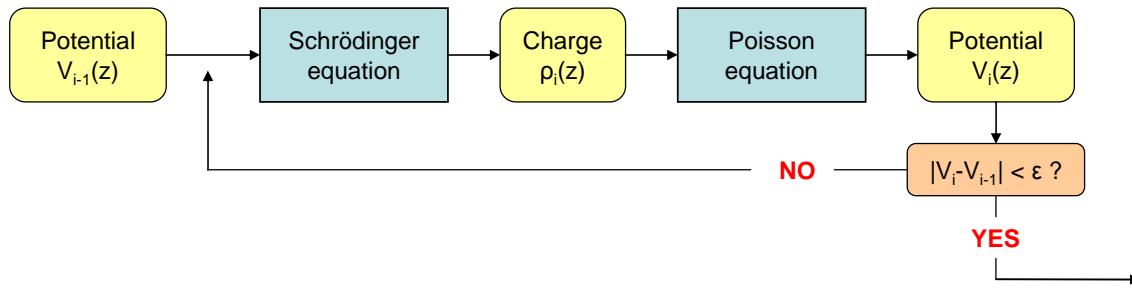


e.g. : nMOS, 0.8nm IL – 2nm  $\text{HfO}_2$  @ $V_g = 3\text{V}$



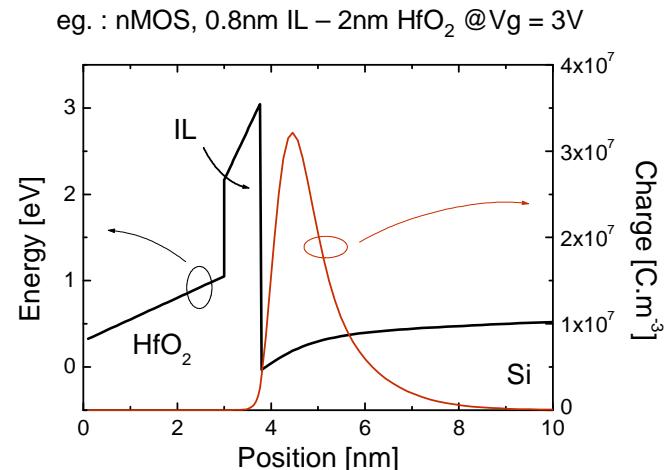
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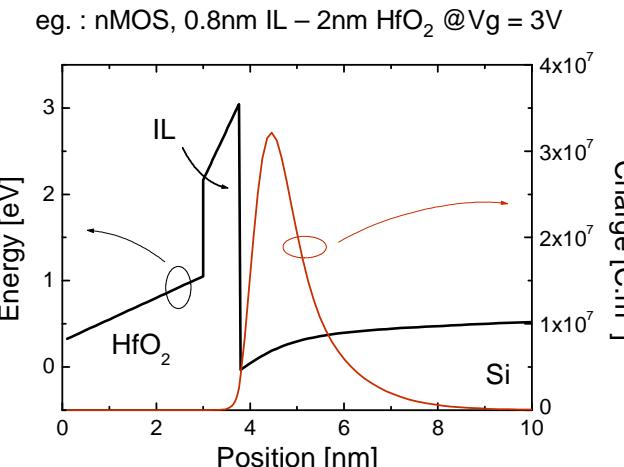
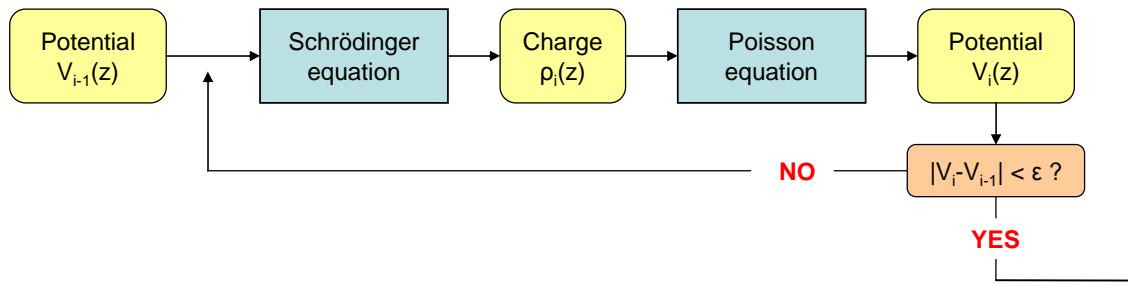
- Dedicated to...

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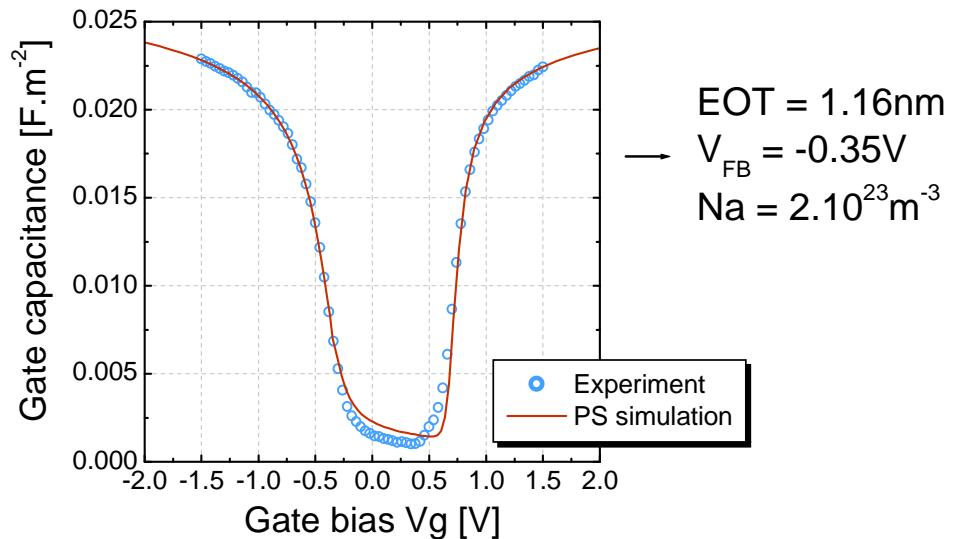
# Poisson-Schrödinger simulation

- Principle



- Dedicated to...

- ... gate current modeling
- ... parameter extraction from  $C(V_g)$  measurements



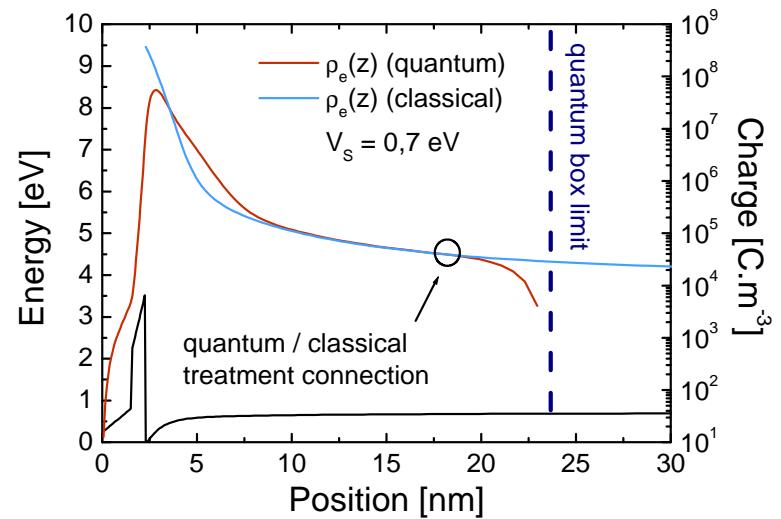
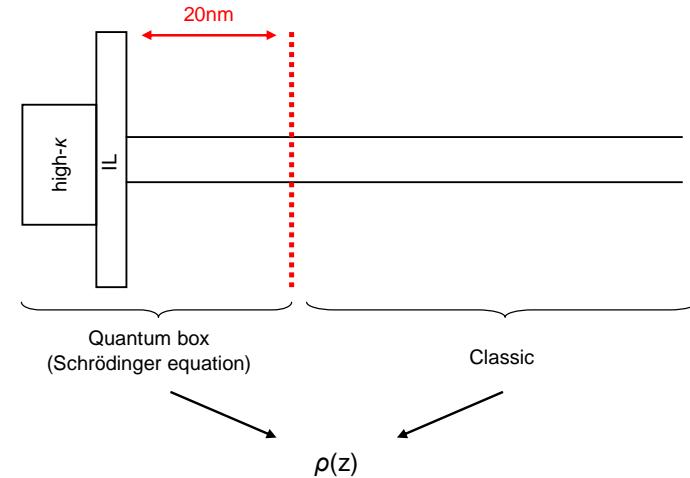
# Poisson-Schrödinger simulation

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- Main features
  - 1D simulation with closed boundaries

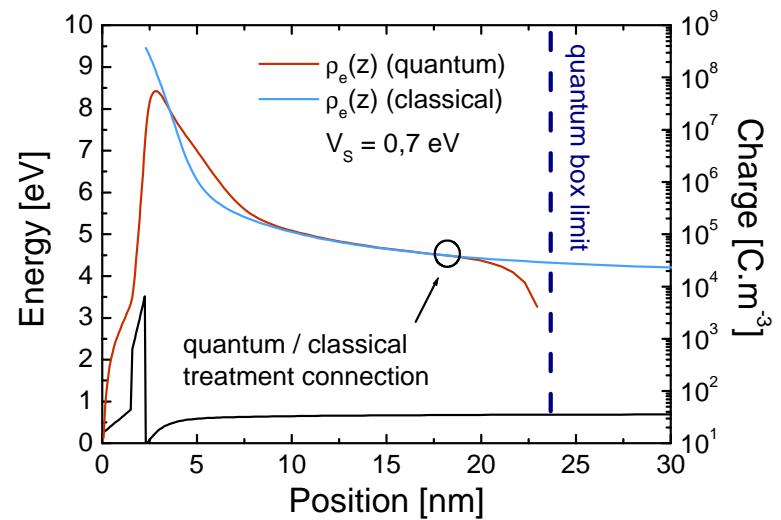
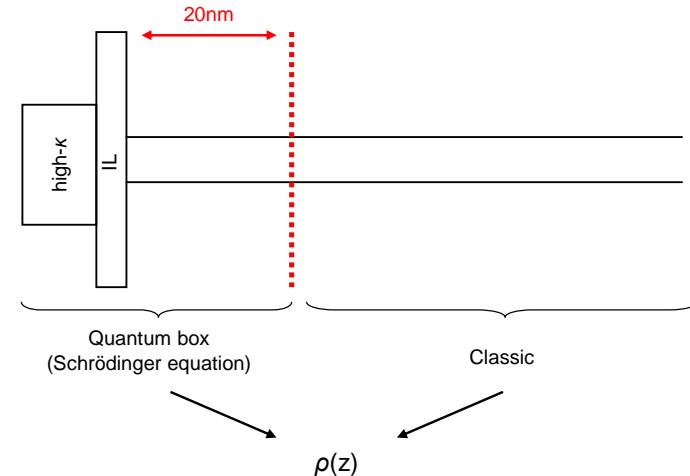
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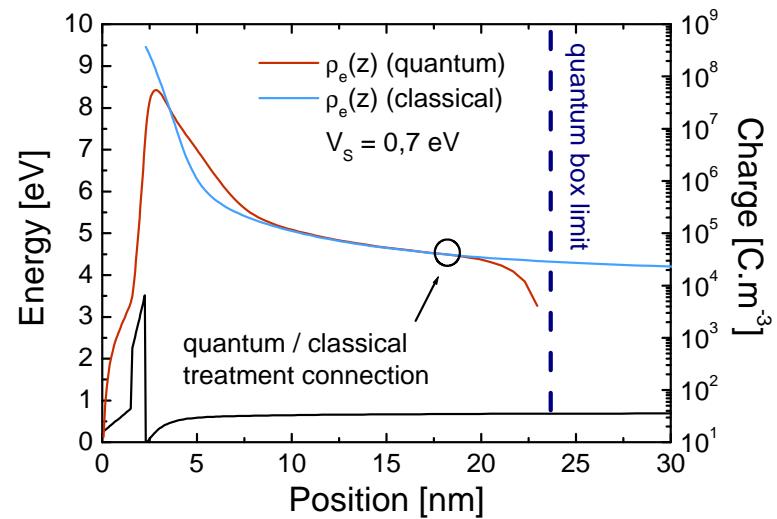
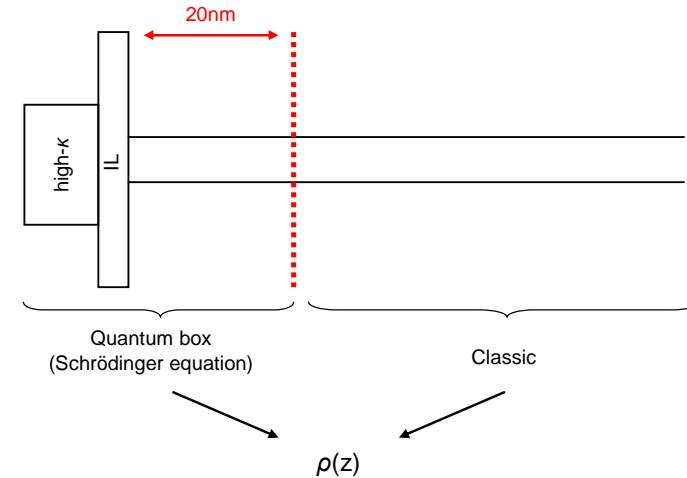
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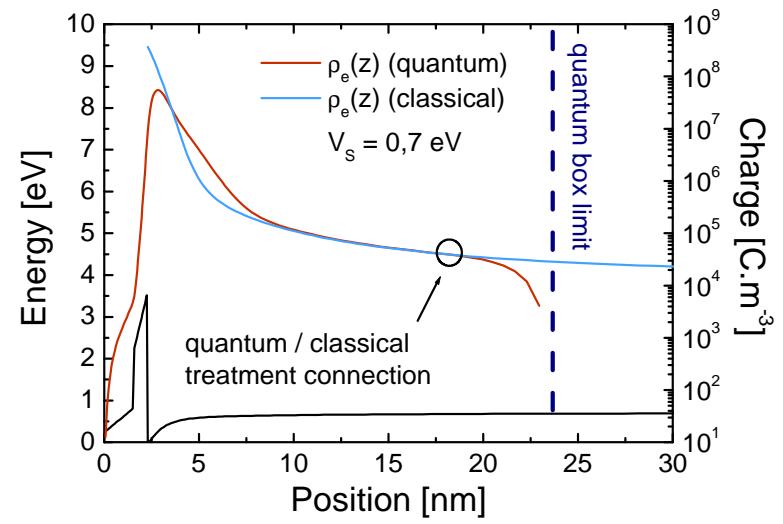
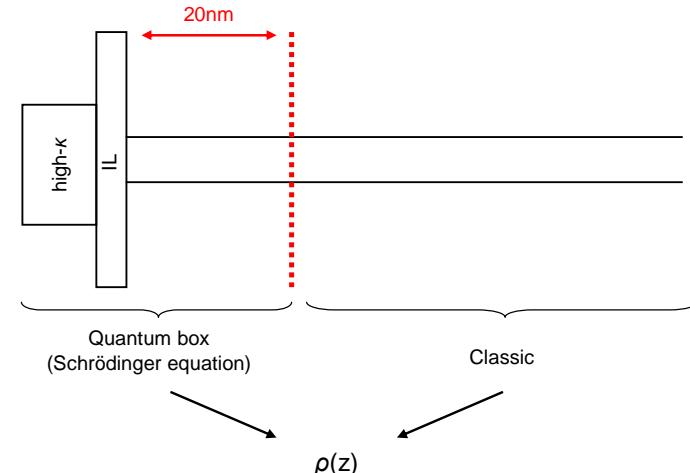
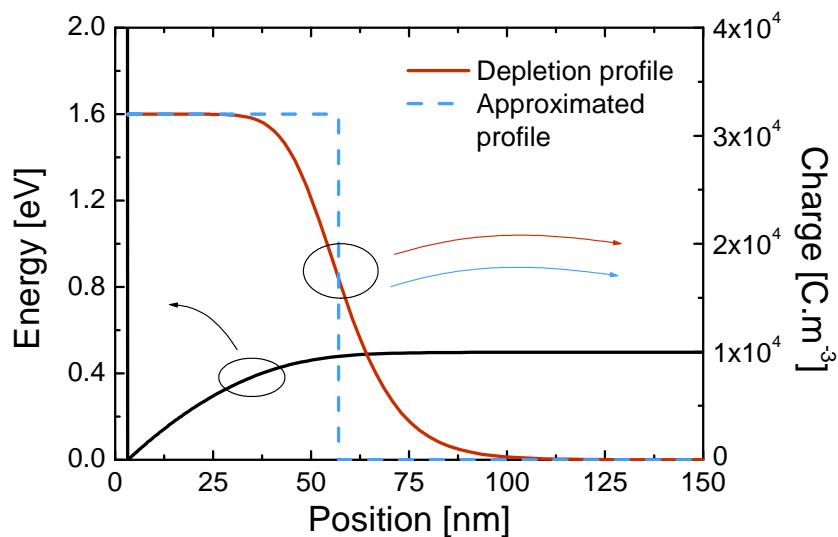
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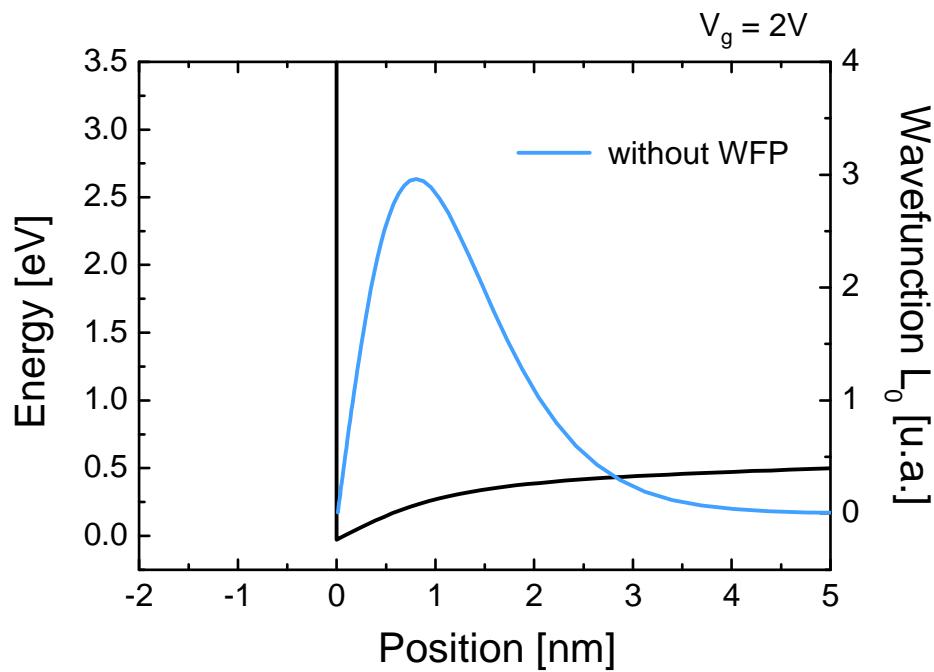
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  - Non-uniform mesh
  - Electrons + holes both considered



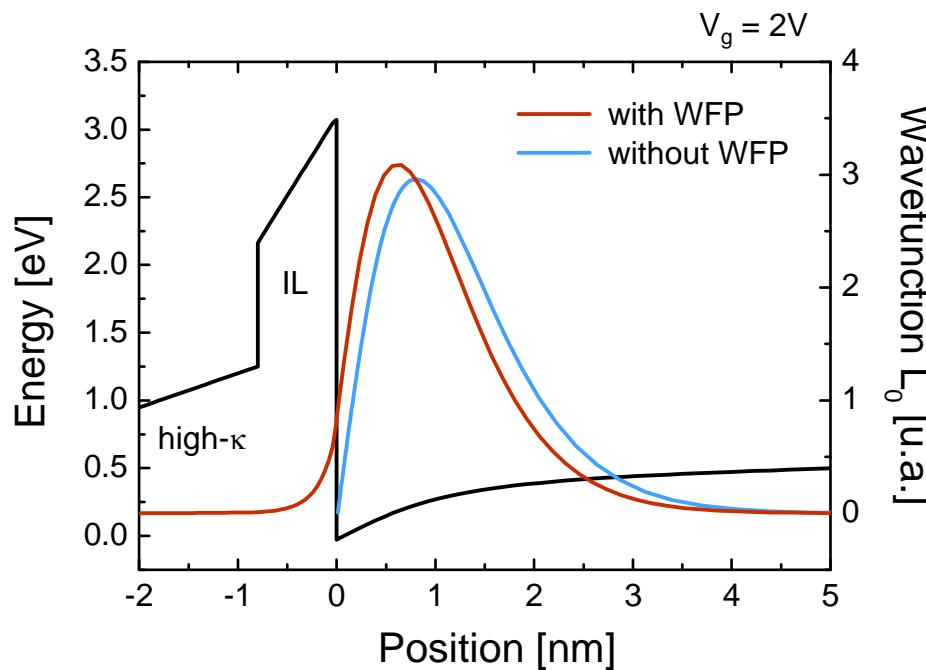
# Poisson-Schrödinger simulation : WFP

- Conventional PS resolution : simulation of Silicon substrate only



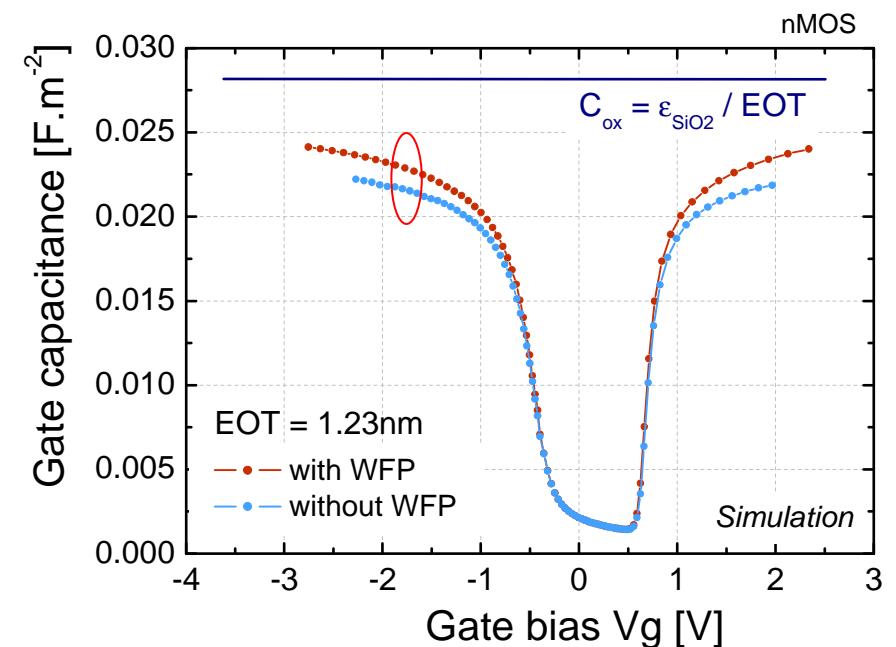
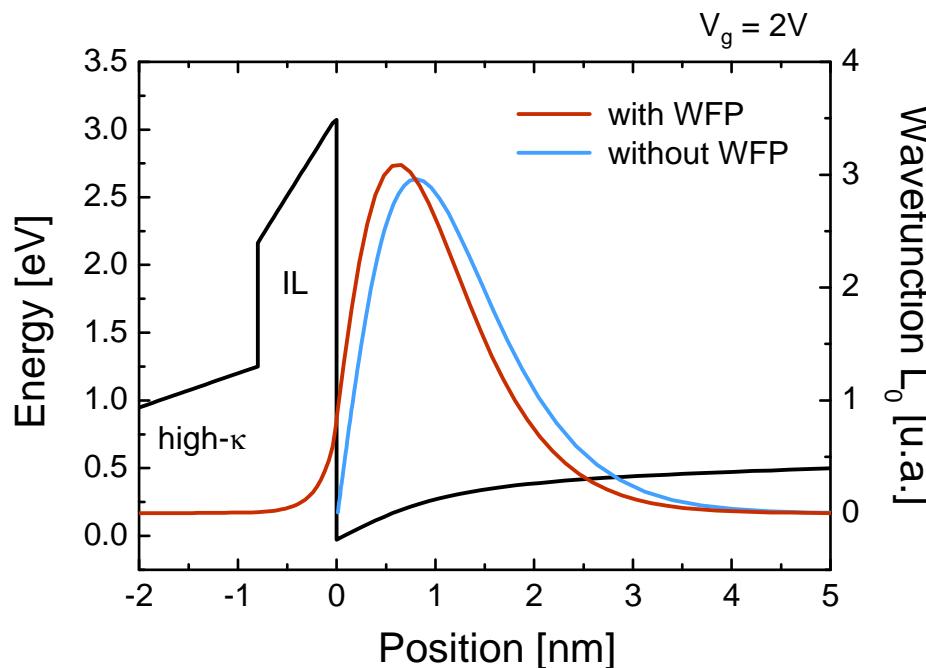
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➔ Without WFP : 1 Å error in EOT extraction

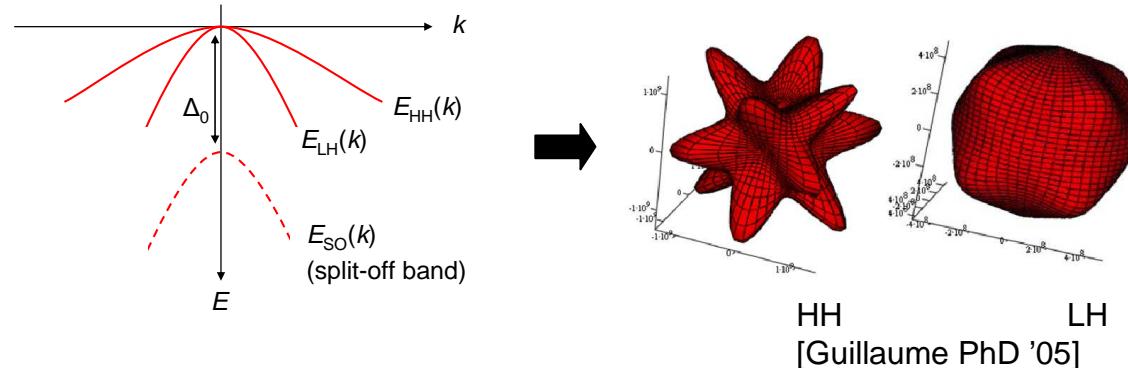
# Poisson-Schrödinger simulation : VB description

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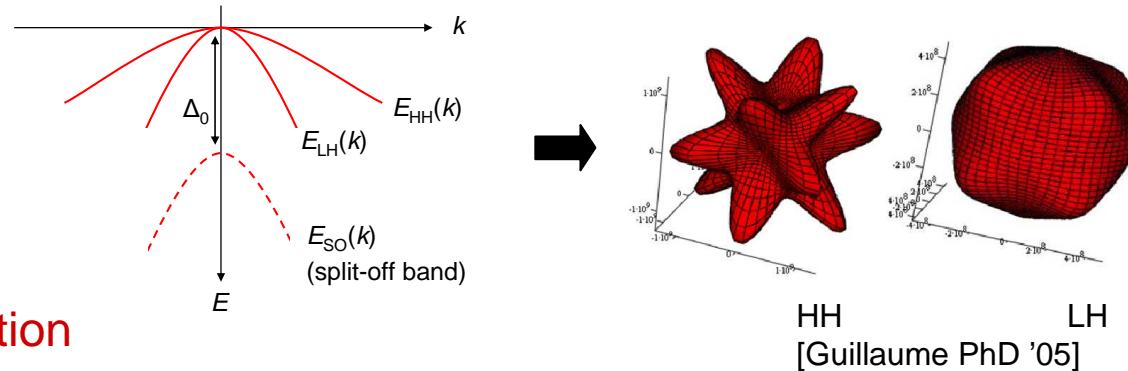
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  - degeneracy
  - anisotropy
  - non-parabolicity



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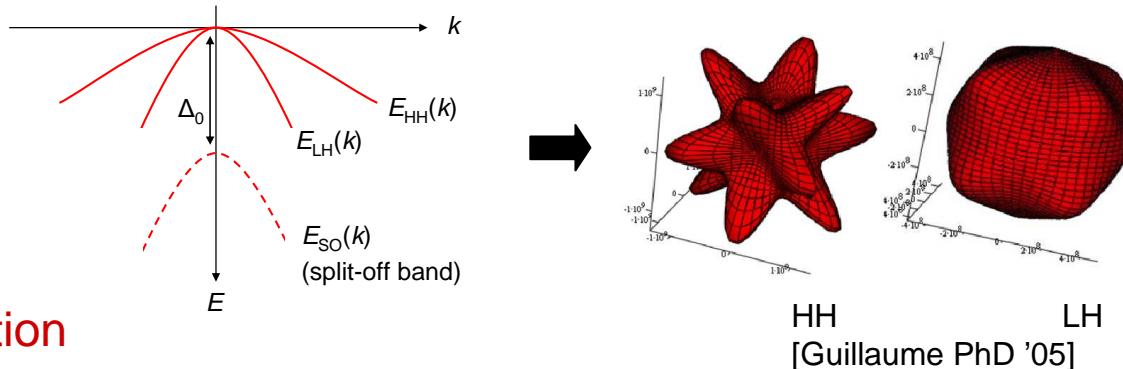
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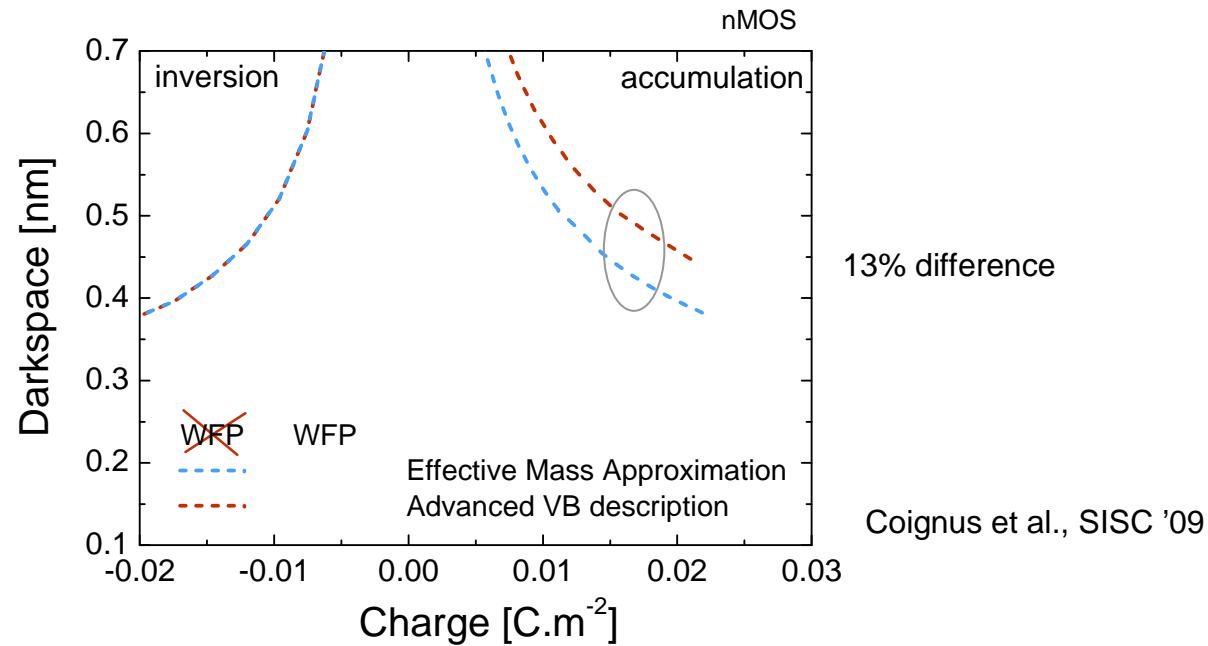
- Main idea: advanced 2D-holes description using analytical E-k fitted on 6x6 k.p results

[DeMichielis et al., IEEE TED 54, 2008]

→ Analytical 2D-holes Density-of-States

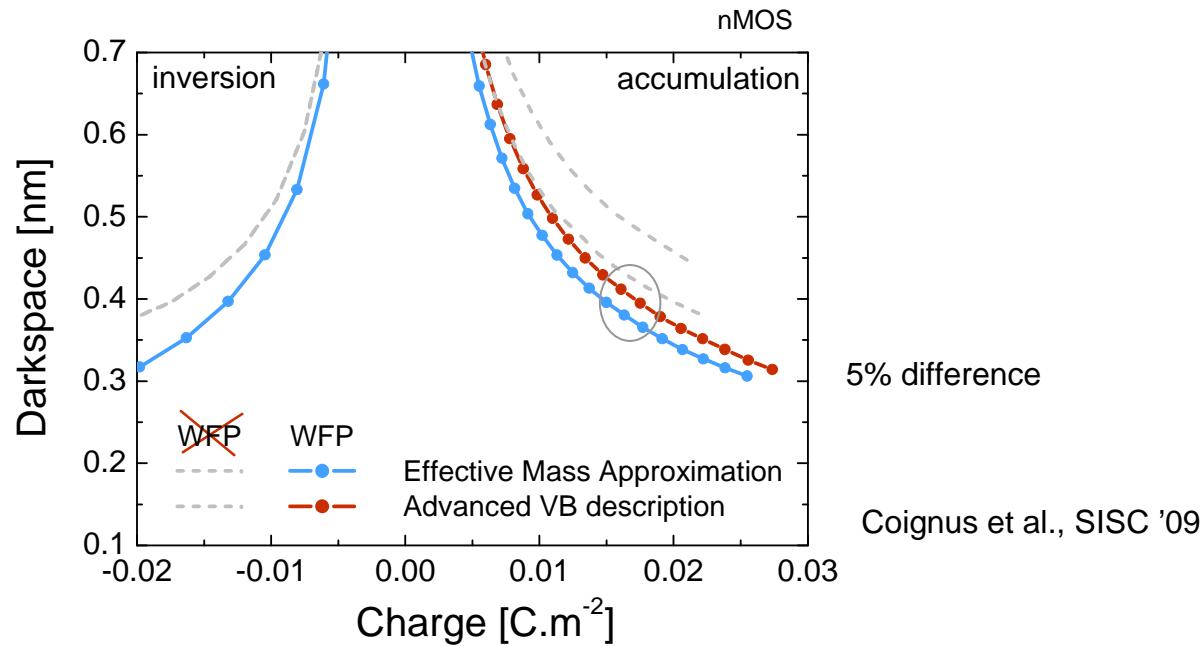
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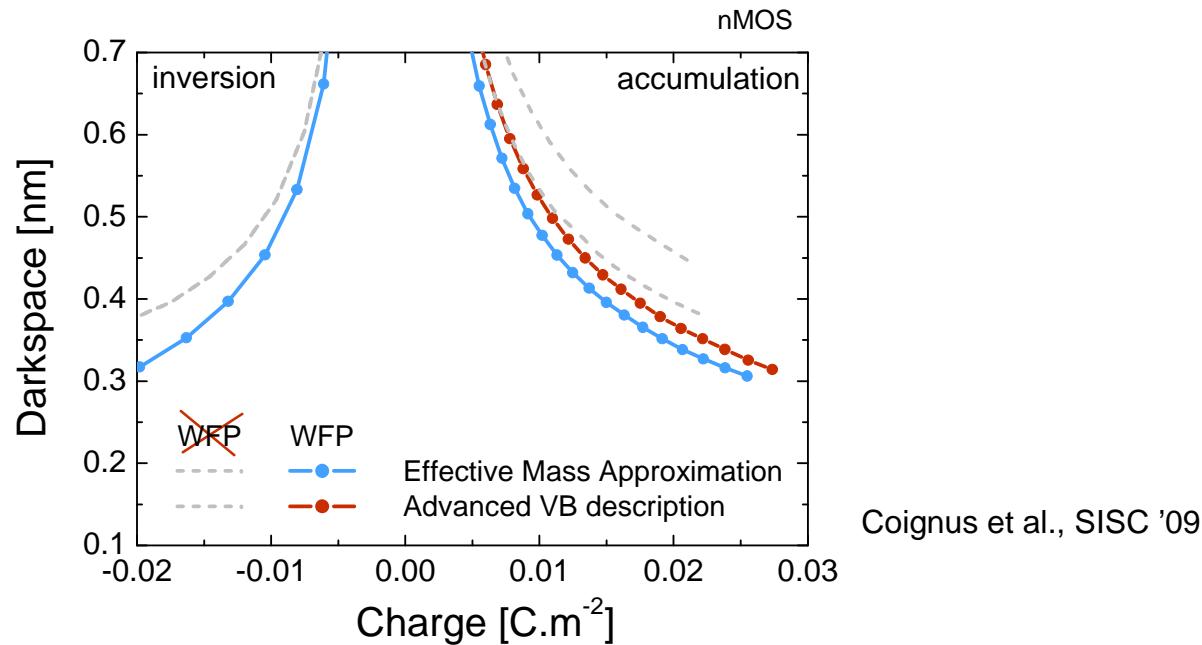
# Poisson-Schrödinger simulation : VB description

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# Poisson-Schrödinger simulation : VB description

- Impact on EOT extraction ?



→ This advanced approach does not significantly impact EOT extraction

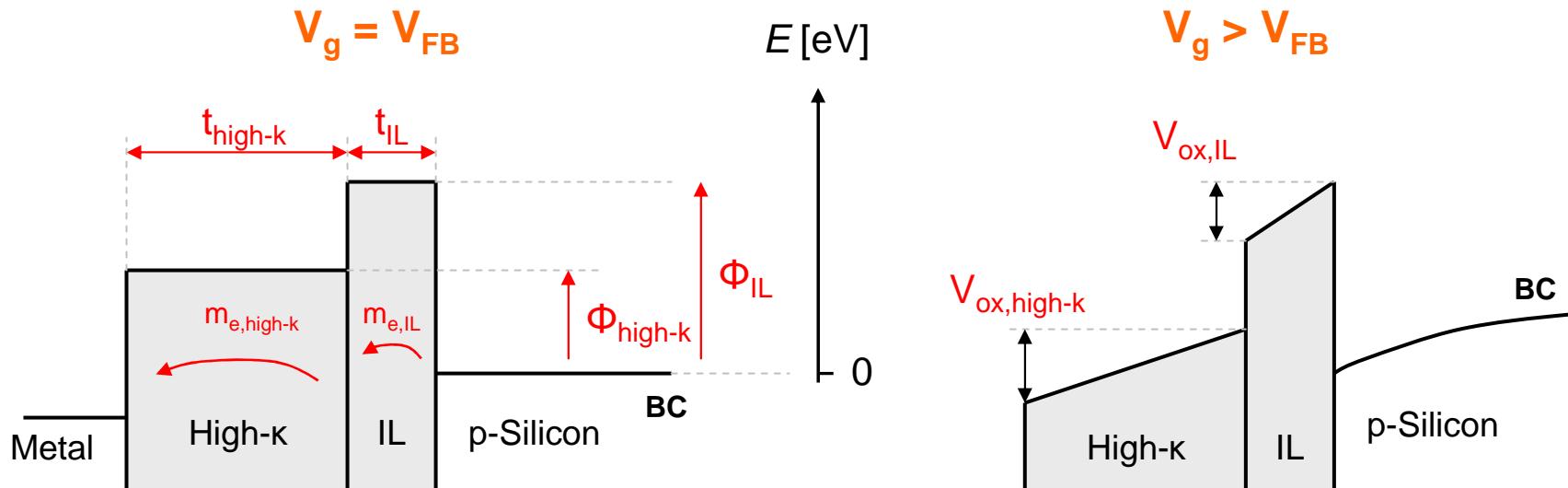
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# Transmission probability modeling

- Transmission probability parameters :

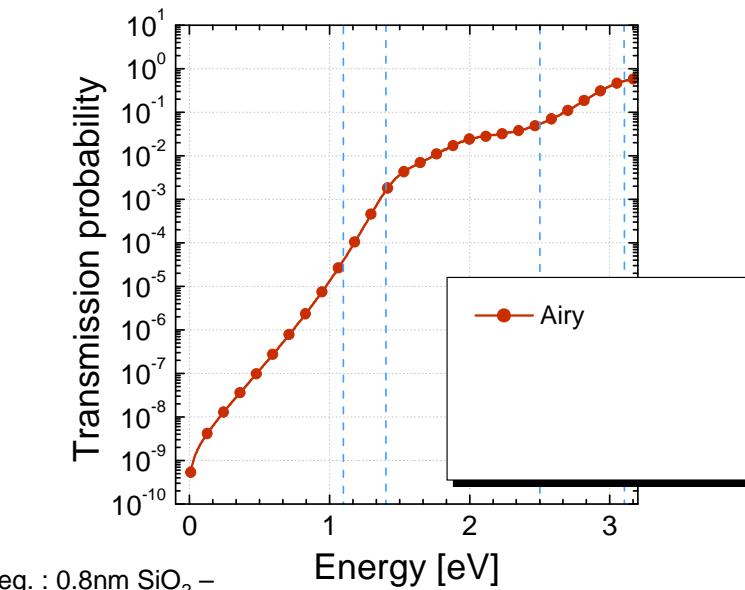
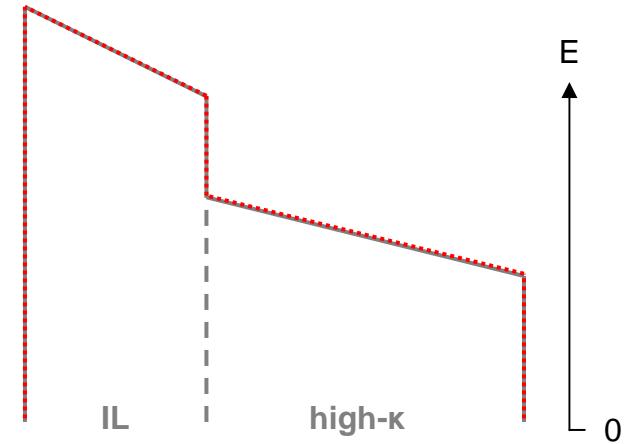


- Several approaches in literature, differing by their accuracy and nature (analytical or numerical)

# Transmission probability modeling

- Airy formalism [Allen JAP '96]
  - Exact solution of Schrödinger equation in a triangular barrier
  - Solving wavefunction continuity at each triangular barrier transition provides T
    - ↑↑ **exact solution**
    - ↓↓ use of Airy function, inadequate to standard compact model libraries

	Analytical approach ?	« Exact » solution
Airy formalism	x	✓

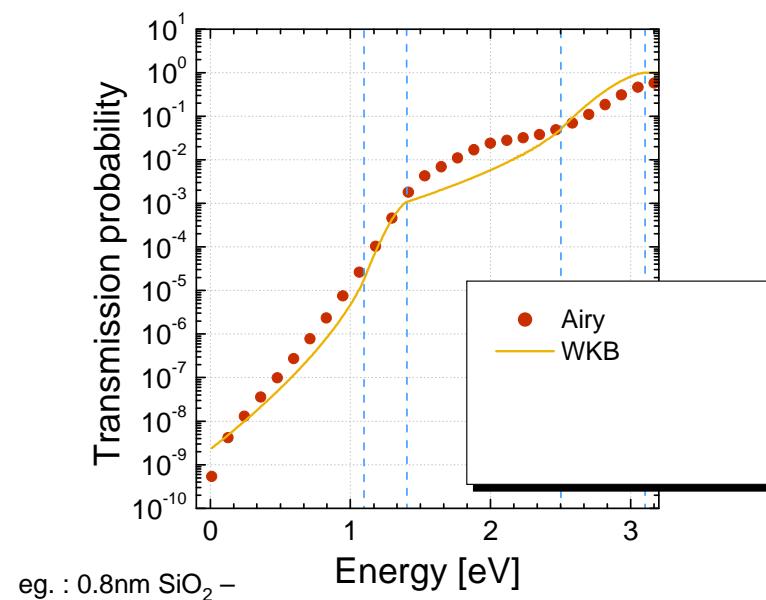
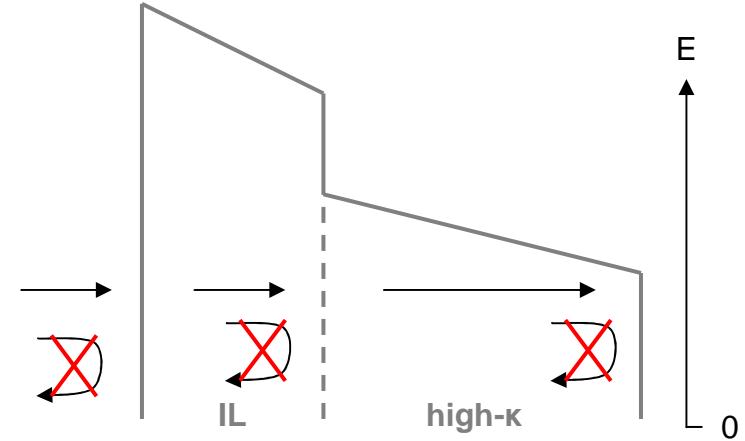


# Transmission probability modeling

- WKB (1926)
  - Analytical method
  - Valid only for smoothly varying potential barriers

↑↑ **analytical approach**  
↓↓ poor accuracy (reflections on potential discontinuities at interfaces not included)

	Analytical approach ?	« Exact » solution
Airy formalism	✗	✓
WKB	✓	✗

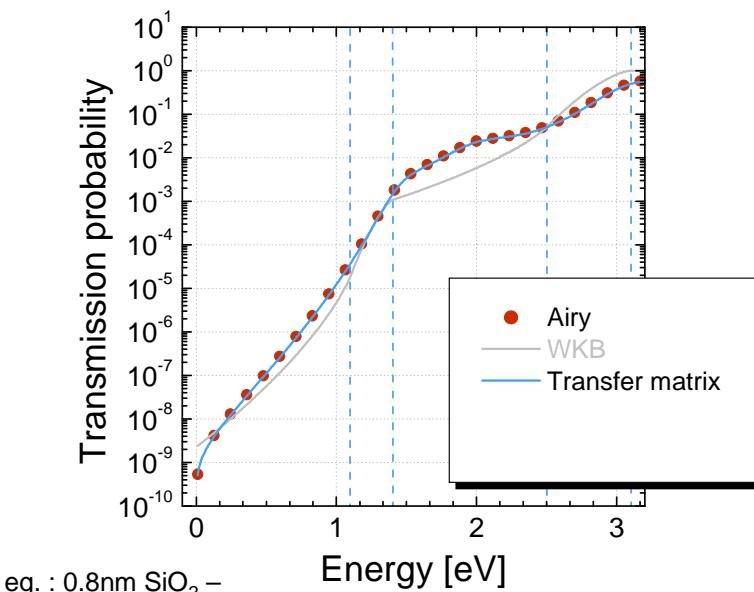
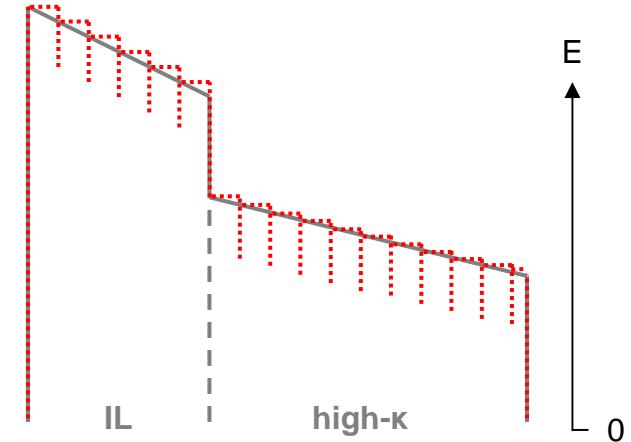


eg. :  $0.8\text{nm SiO}_2 - 2\text{nm HfO}_2$

# Transmission probability modeling

- Transfer matrix [Ando JAP '87]
  - Computational method: discretization of an arbitrary barrier by N square barriers
  - Solving wavefunction continuity at each square barrier transition provides T
    - ↑↑ accuracy ( $N > 20$ )
    - ↓↓ numerical approach, computational time

	Analytical approach ?	« Exact » solution
Airy formalism	✗	✓
WKB	✓	✗
Transfer matrix	✗	≈



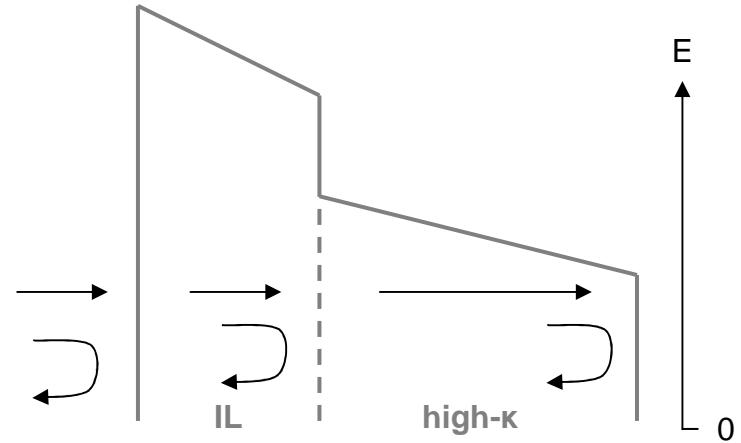
# Transmission probability modeling

- Advanced WKB
  - Extended from WKB analytical formula
  - Provides multiplicative factor correcting for potential discontinuities

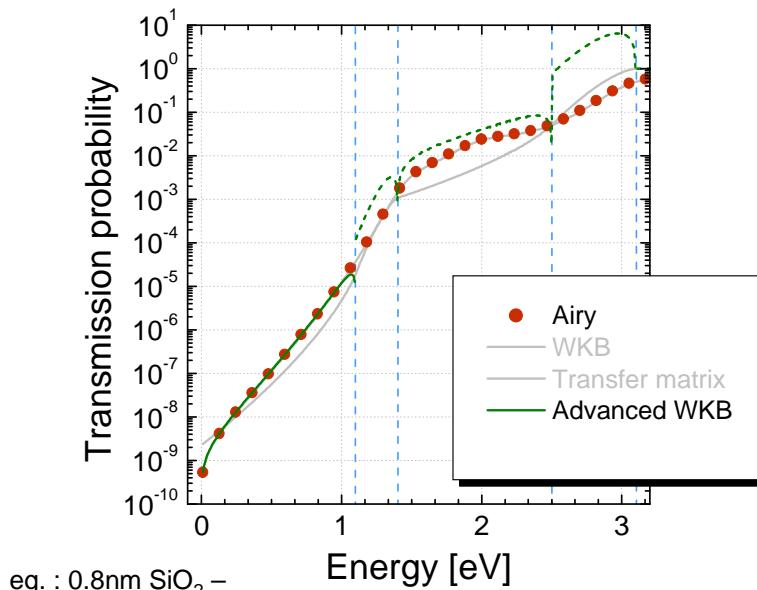
↑↑ **analytical approach**

↑↑ **accuracy**

↓↓ **validity : Direct Tunneling only**



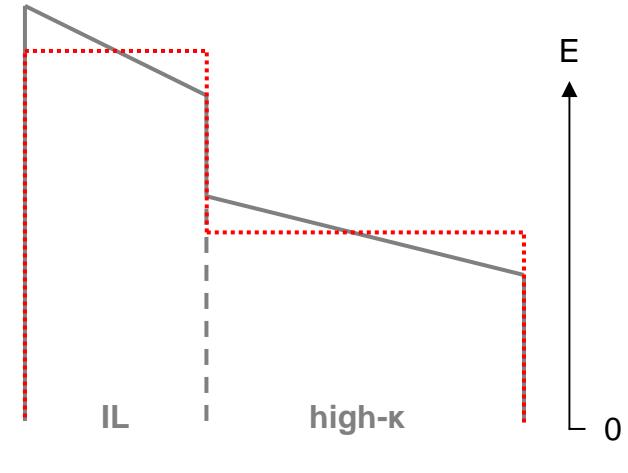
	Analytical approach ?	« Exact » solution
Airy formalism	✗	✓
WKB	✓	✗
Transfer matrix	✗	≈
Advanced WKB	✓	≈



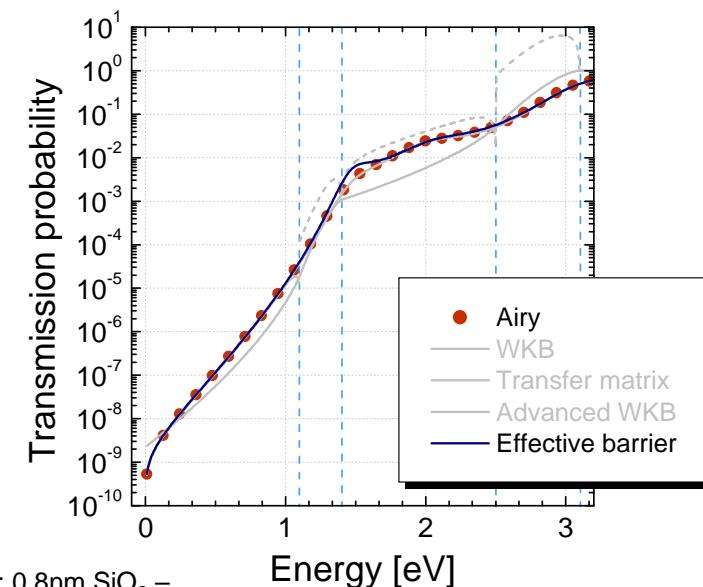
# Transmission probability modeling

- Effective barrier height approximation
  - Exact solution of Schrödinger equation in a squares barriers
  - Solving wavefunction continuity at each triangular barrier transition provides T
    - $\uparrow\uparrow$  **analytical approach**
    - $\uparrow\uparrow$  **accuracy in DT regime**
    - $\downarrow\downarrow$  may lead to important error around TD – FN transitions

	Analytical approach ?	« Exact » solution
Airy formalism	x	✓
WKB	✓	x
Transfer matrix	x	≈
Advanced WKB	✓	≈
Effective barrier	✓	≈



Coignus et al., JVST B '09



eg. : 0.8nm SiO<sub>2</sub> –  
2nm HfO<sub>2</sub>

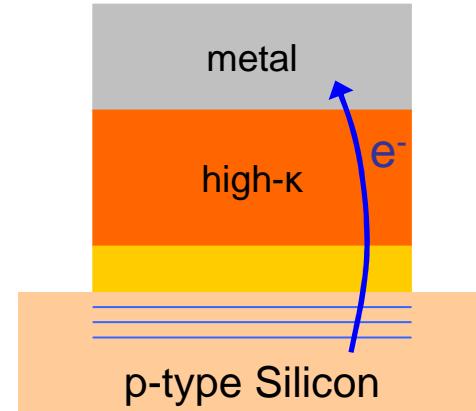
# Outline

---

- **Tunneling current modeling**
  - Self-consistent Poisson-Schrödinger simulation
  - Transmission probability
- **Experimental investigation of leakage current in  $\text{HfO}_2$  gate stacks**
  - Transport mechanisms
  - Dielectric thicknesses extraction
  - Tunneling parameters extraction
  - Dipole effect in Mg-capped  $\text{HfO}_2$  gate stacks
- **Conclusions**

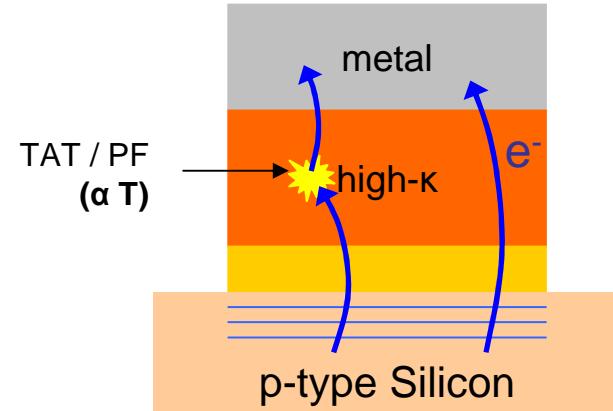
# Gate leakage mechanisms in $\text{HfO}_2$ gate stacks

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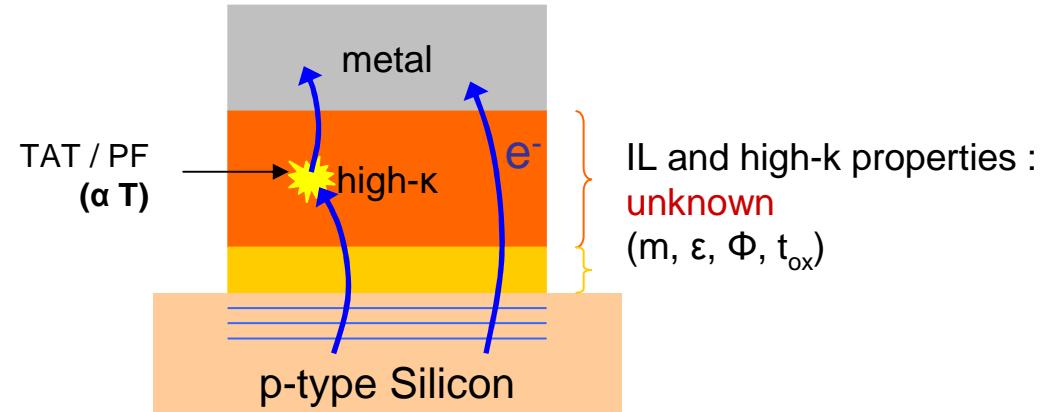


# Gate leakage mechanisms in $\text{HfO}_2$ gate stacks

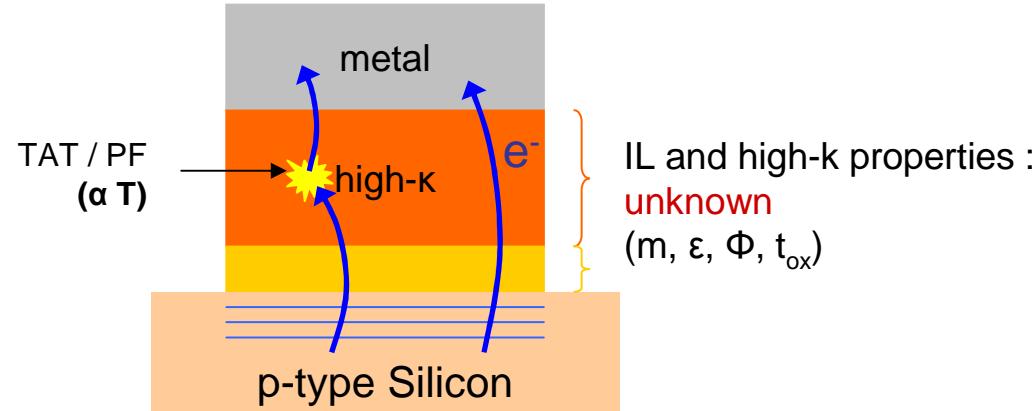
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# Gate leakage mechanisms in $\text{HfO}_2$ gate stacks



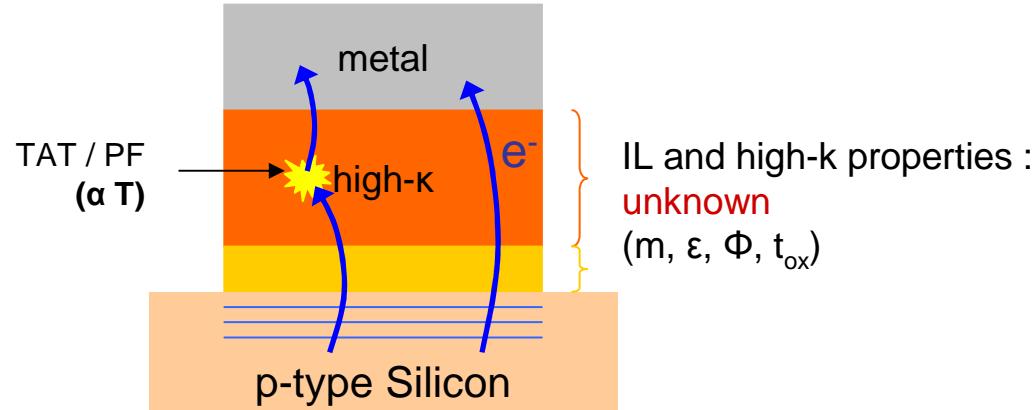
# Gate leakage mechanisms in $\text{HfO}_2$ gate stacks



- **Issue 1 :** Identification of transport mechanisms

$$J_{total} = \underbrace{J_{direct\ tunneling\ current}}_{\text{Depends on T only via } Q_{sc}(T)} + \underbrace{J_{temperature/trap\ assisted\ current}}_{Q_{sc}(T) \text{ dependant} + \text{temperature assisted}}$$

# Gate leakage mechanisms in $\text{HfO}_2$ gate stacks



- **Issue 1 :** Identification of transport mechanisms

$$J_{total} = \underbrace{J_{direct\ tunneling\ current}}_{\text{Depends on } T \text{ only via } Q_{sc}(T)} + \underbrace{J_{temperature/trap\ assisted\ current}}_{Q_{sc}(T) \text{ dependant} + \text{temperature assisted}}$$

→ low / high temperature measurements at constant  $Q_{sc}$  (i.e. field)

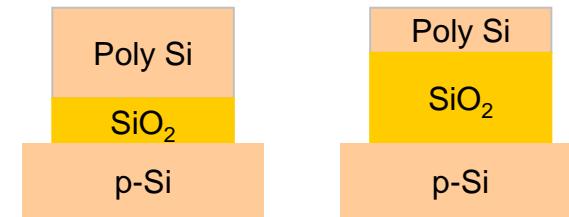
# Transport mechanisms : methodology

---

## 1. Several nMOS transistors tested

- p Silicon / RTO **SiO<sub>2</sub>** / n+ Polysilicon  
*(ref. samples)*

$$t_{\text{SiO}_2} = 1.5 / 2.5 \text{ nm}$$

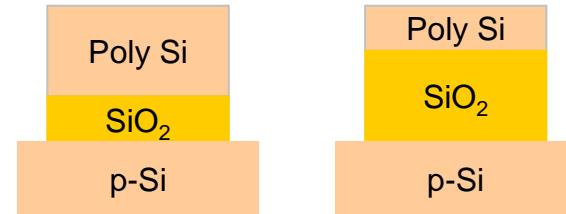


# Transport mechanisms : methodology

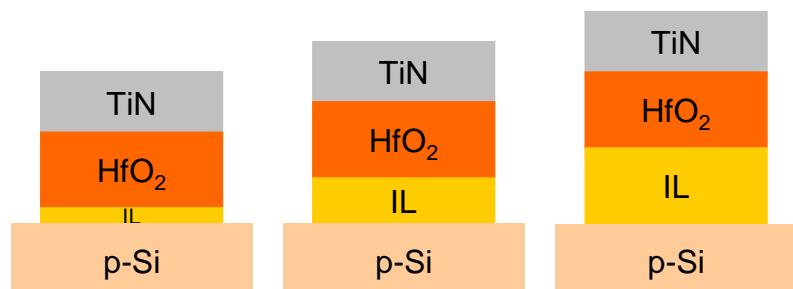
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- p Silicon / IL / ALD HfO<sub>2</sub> / CVD TiN



$$t_{\text{IL}} (\text{RTO}) = 1.2 / 1.5 / 2.0 \text{ nm}$$

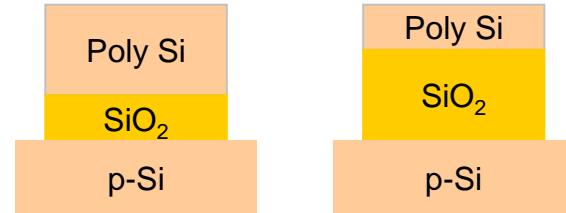
$$t_{\text{HfO}_2} = \text{cte} = 3 \text{ nm}$$

# Transport mechanisms : methodology

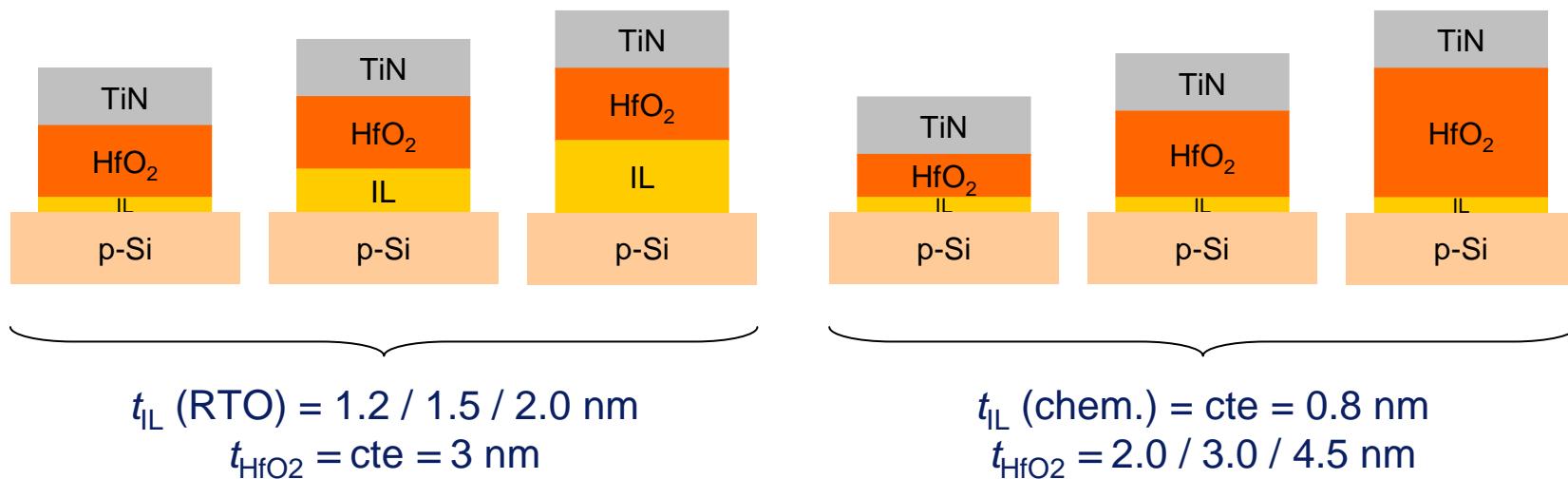
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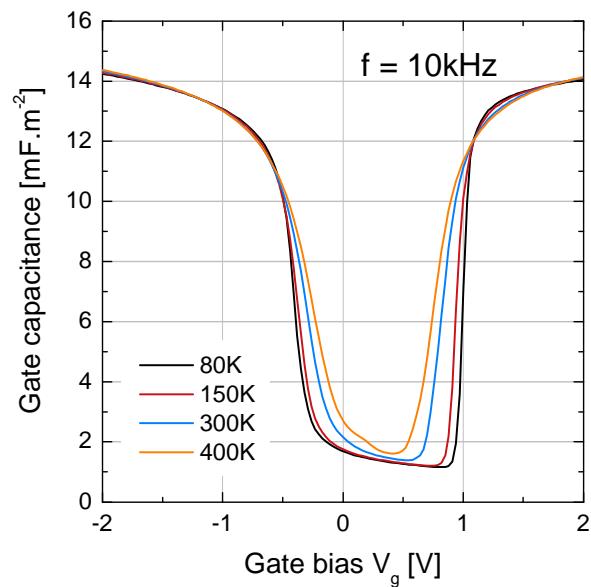
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# Transport mechanisms : methodology

## 2. C ( $V_g$ ) measurements from 80 to 400K

- Parameters extraction by fitting Poisson-Schrödinger results : EOT, Na,  $V_{FB}$
- Experimental charge extraction  $Q(V_g) = \int_{V_{fb}}^{V_g} C(u) du$



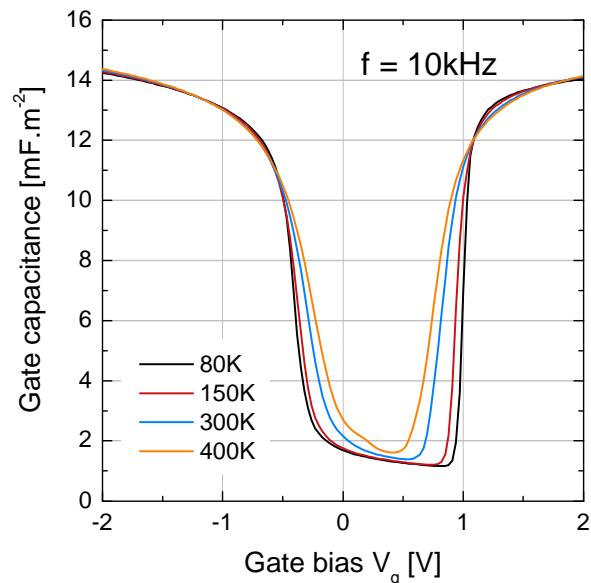
example :  
12Å IL - 30Å  
 $HfO_2$  gate  
stack

# Transport mechanisms : methodology

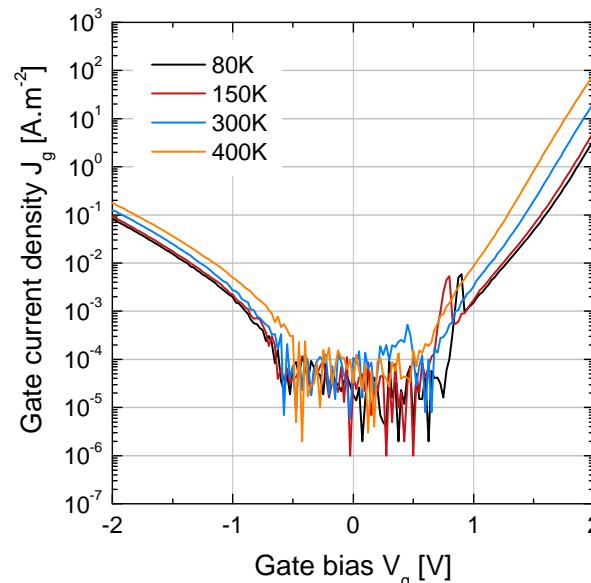
## 2. $C(V_g)$ measurements from 80 to 400K

- Parameters extraction by fitting Poisson-Schrödinger results : EOT, Na,  $V_{FB}$
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12Å IL - 30Å  
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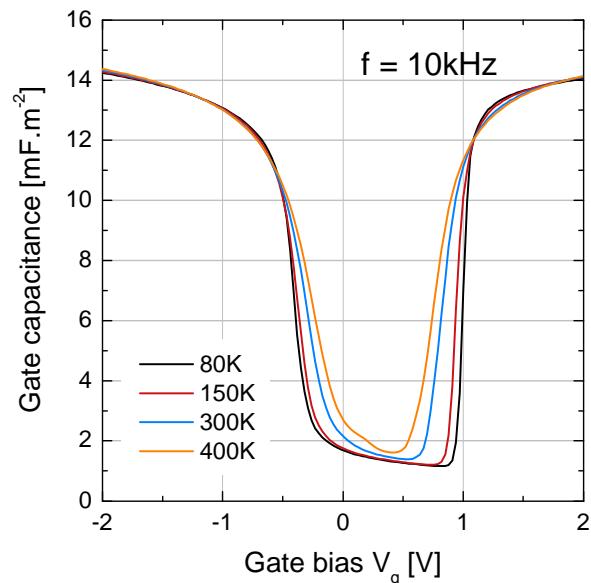
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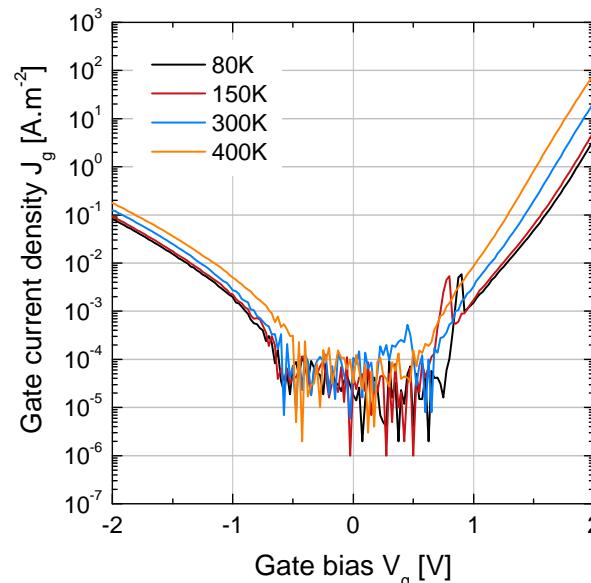
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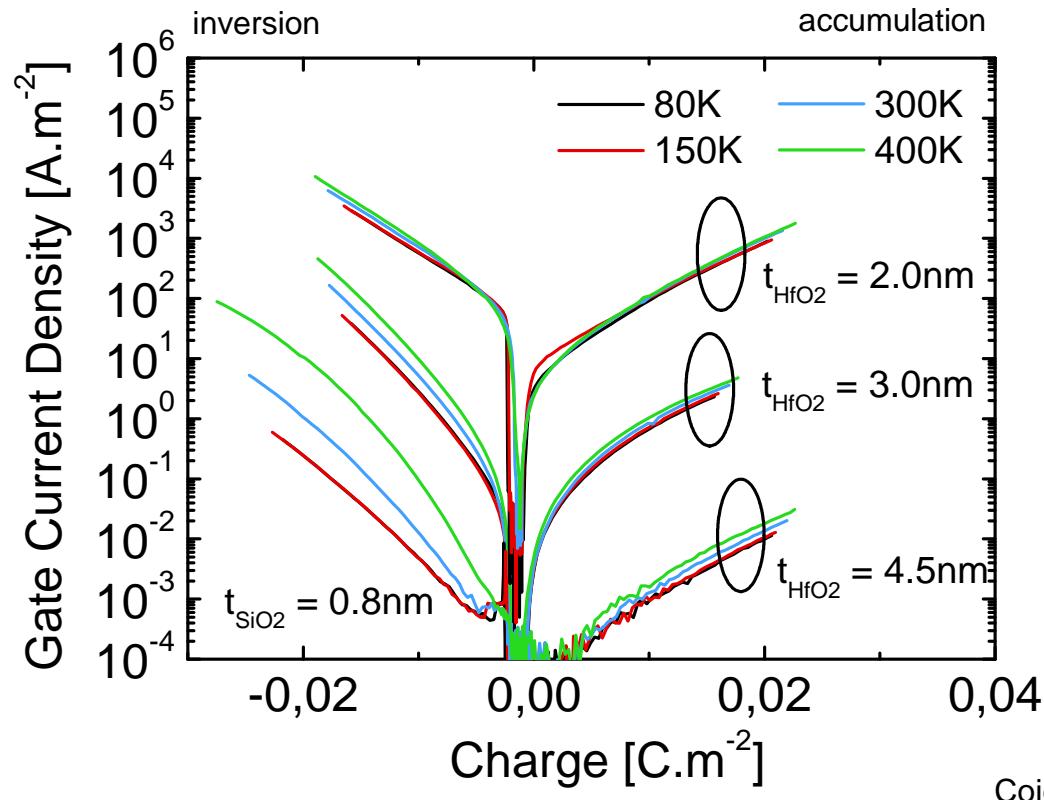
→  $I_g (Q_{sc})$  plots



example :  
12 Å IL - 30 Å  
 $HfO_2$  gate  
stack



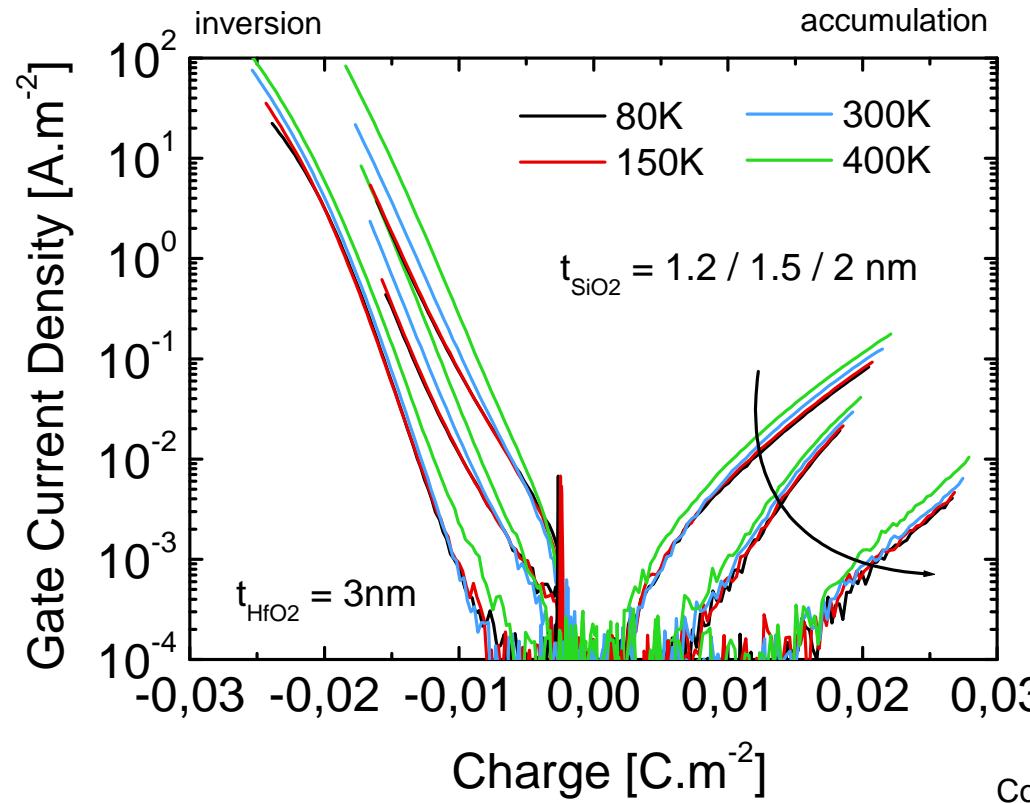
# Transport mechanisms : electrical results



Coignus et al., ESSDERC '09

- Accumulation regime ( $Q > 0$ ) : no temperature activation...
- Inversion regime ( $Q < 0$ ) : thermally-assisted current for thick stacks

# Transport mechanisms : electrical results



Coignus et al., ESSDERC '09

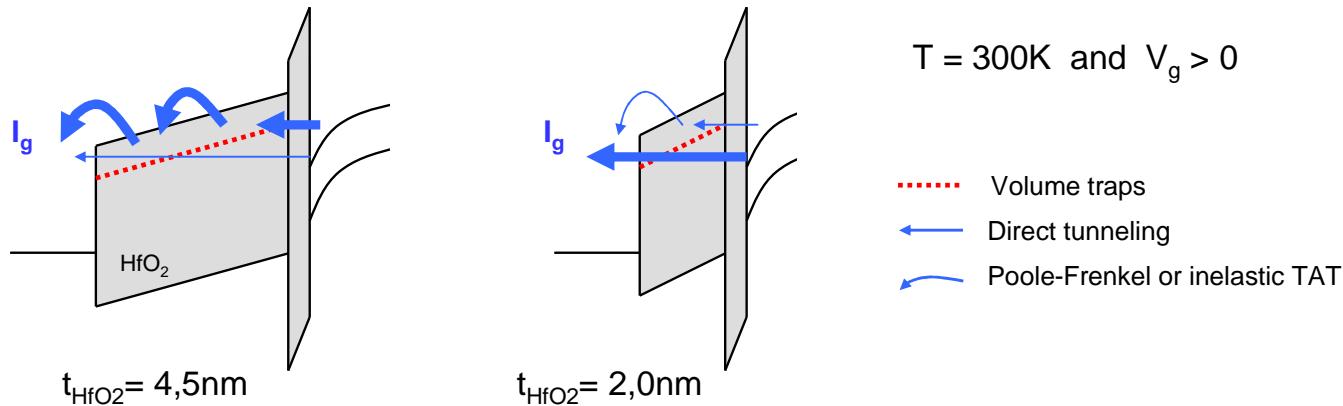
- Accumulation regime ( $Q > 0$ ) : no temperature activation...
- Inversion regime ( $Q < 0$ ) : constant thermally-assisted component

# Transport mechanisms

- **Conclusion on Issue 1 :** Identification of transport mechanisms

Presence of a thermally-assisted contribution in  $\text{HfO}_2$

- In nMOS inversion regime (electrons)
- On thick layers ( $t_{\text{HfO}_2} > 3\text{nm}$ ) (due to volume trap)

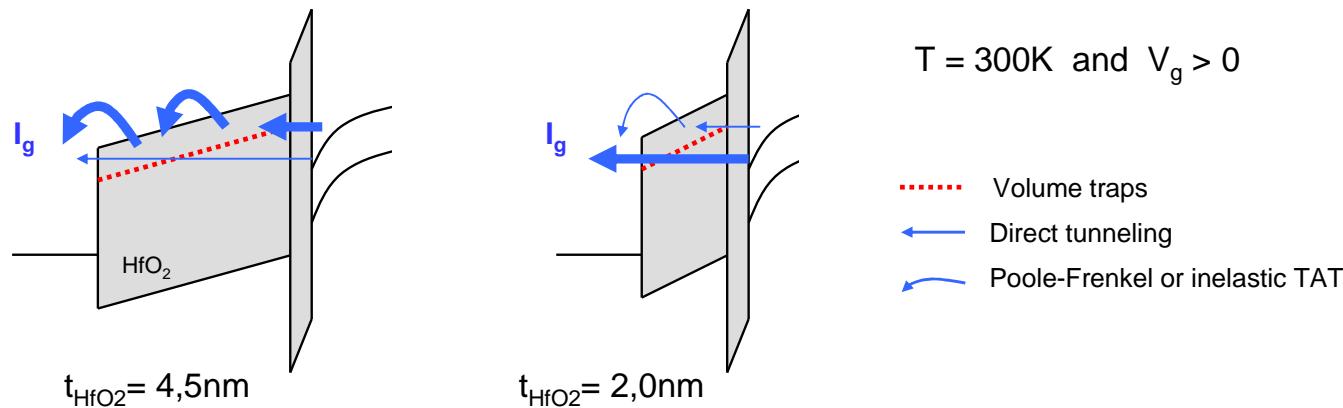


# Transport mechanisms

- **Conclusion on Issue 1 :** Identification of transport mechanisms

Presence of a thermally-assisted contribution in  $\text{HfO}_2$

- In nMOS inversion regime (electrons)
- On thick layers ( $t_{\text{HfO}_2} > 2.5\text{nm}$ ) (due to volume trap)



- **Issue 2 :** Can current @ low temperature be explained by DT model ?

→ Comparison with simulation, accurate extraction of dielectric parameters

**Purpose :** explain the **whole** set of experiments with a **single** set of parameters

# Outline

---

- **Tunneling current modeling**
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  - Tunneling parameters extraction
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# Dielectric thicknesses extraction

---

$$EOT = \epsilon_{SiO_2} \cdot \left( \frac{t_{IL}}{\epsilon_{IL}} + \frac{t_{HfO_2}}{\epsilon_{HfO_2}} \right)$$

# Dielectric thicknesses extraction

---

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Extracted from  $C(V_g)$   
measurements

# Dielectric thicknesses extraction

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$$\text{EOT} = \epsilon_{\text{SiO}_2} \cdot \left( \frac{t_{\text{IL}}}{\epsilon_{\text{IL}}} + \frac{t_{\text{HfO}_2}}{\epsilon_{\text{HfO}_2}} \right) \rightarrow \text{ALD deposition : assumed equal to target value}$$

**EOT** =  $\epsilon_{\text{SiO}_2} \cdot \left( \frac{t_{\text{IL}}}{\epsilon_{\text{IL}}} + \frac{t_{\text{HfO}_2}}{\epsilon_{\text{HfO}_2}} \right)$

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Extracted from  $C(V_g)$  measurements

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3 unknowns...

→ samples with IL/HfO<sub>2</sub> thickness variants : permittivity extraction

# Dielectric thicknesses extraction

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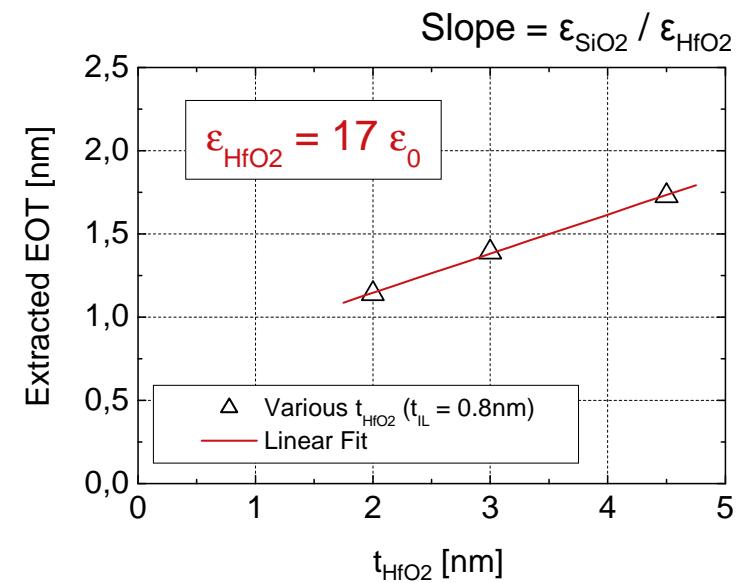
ALD deposition : assumed equal to target value

$17 \epsilon_0$

2 unknowns...

→ samples with IL/HfO<sub>2</sub> thickness variants : permittivity extraction

- HfO<sub>2</sub> permittivity extraction



# Dielectric thicknesses extraction

$$\text{EOT} = \epsilon_{\text{SiO}_2} \cdot \left( \frac{t_{\text{IL}}}{\epsilon_{\text{IL}}} + \frac{t_{\text{HfO}_2}}{\epsilon_{\text{HfO}_2}} \right)$$

Extracted from  $C(V_g)$  measurements

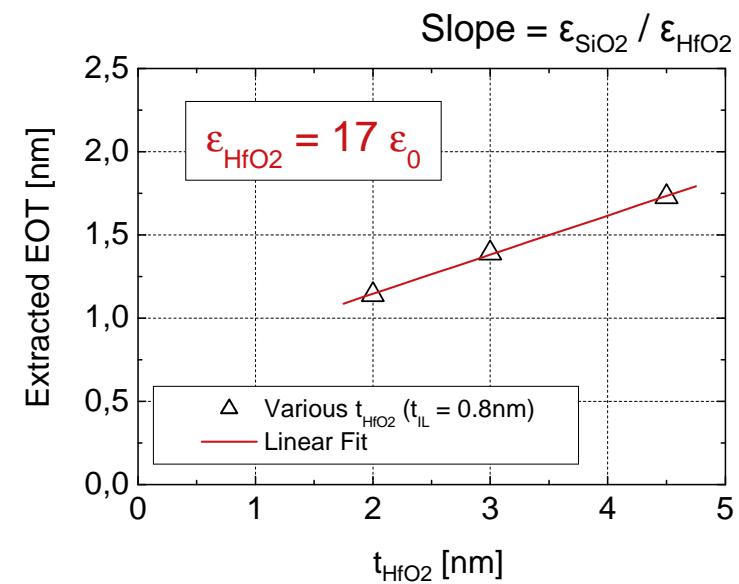
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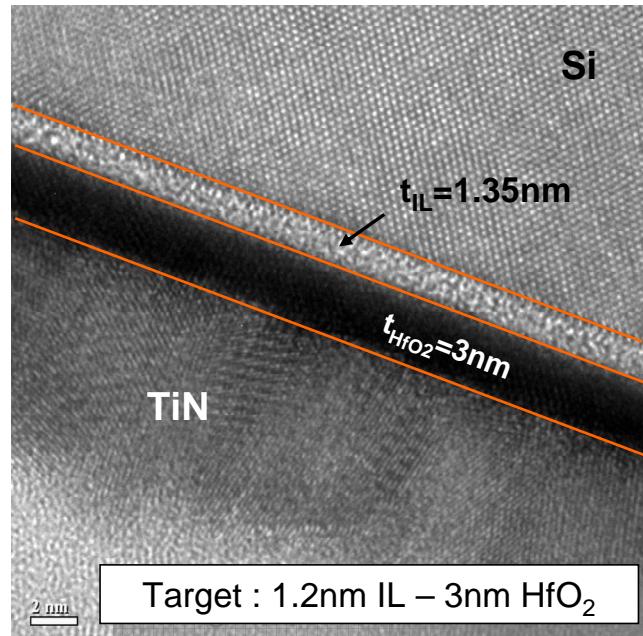
→ samples with IL/HfO<sub>2</sub> thickness variants : permittivity extraction

- HfO<sub>2</sub> permittivity extraction
- IL issue :
  - permittivity may differ from  $\epsilon_{\text{SiO}_2} = 3.9\epsilon_0$
  - thickness may be different from target value...

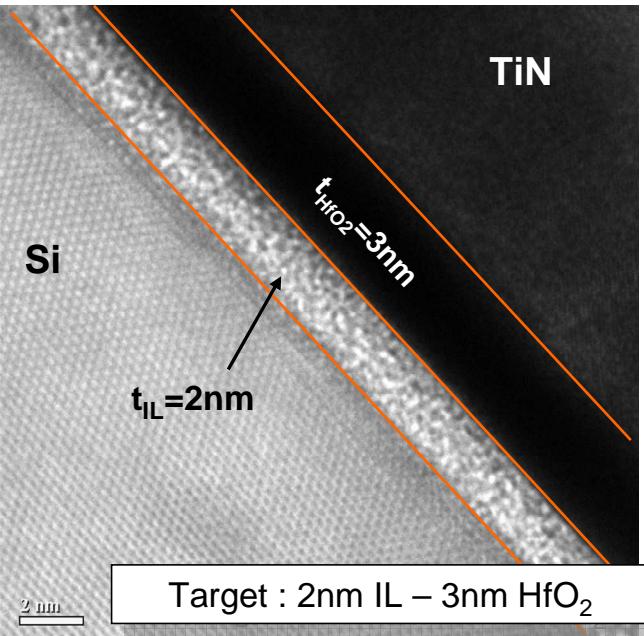


# Dielectric thicknesses extraction

- TEM observations on RTO IL devices



$$t_{\text{target}} \neq t_{\text{measured}}$$

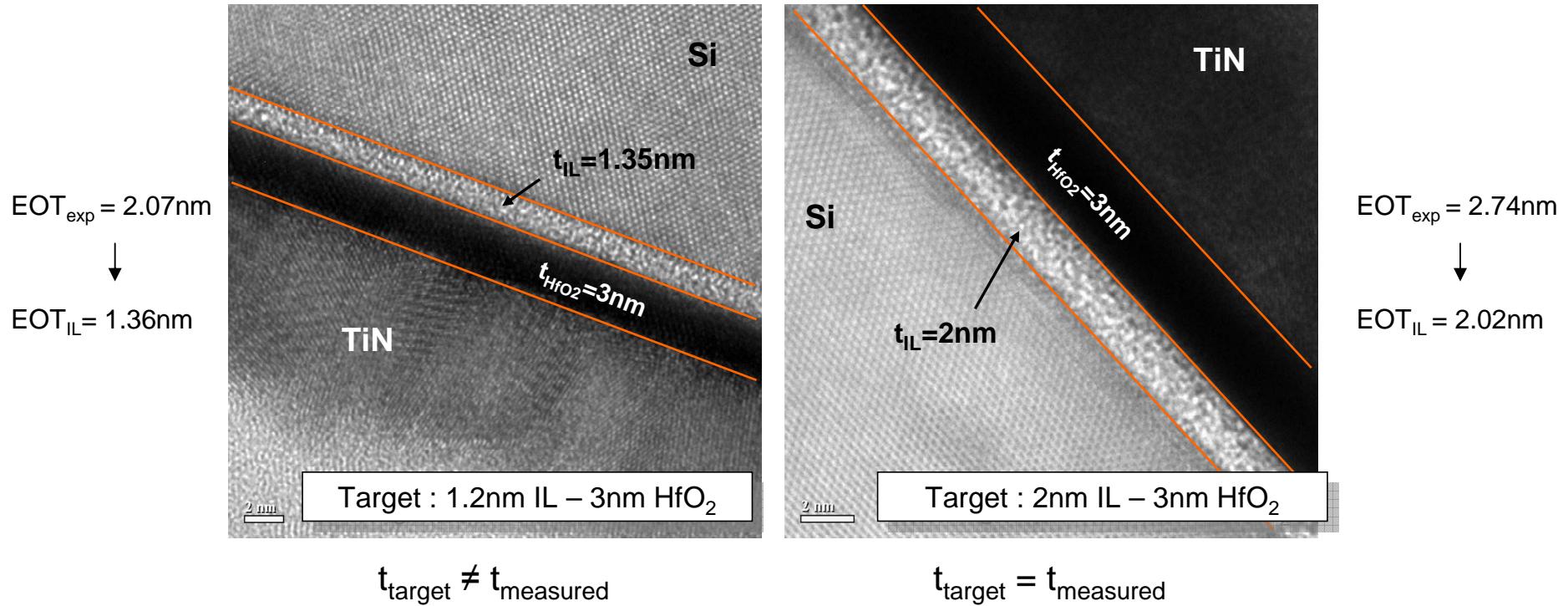


$$t_{\text{target}} = t_{\text{measured}}$$

Coignus et al., SSE '10

# Dielectric thicknesses extraction

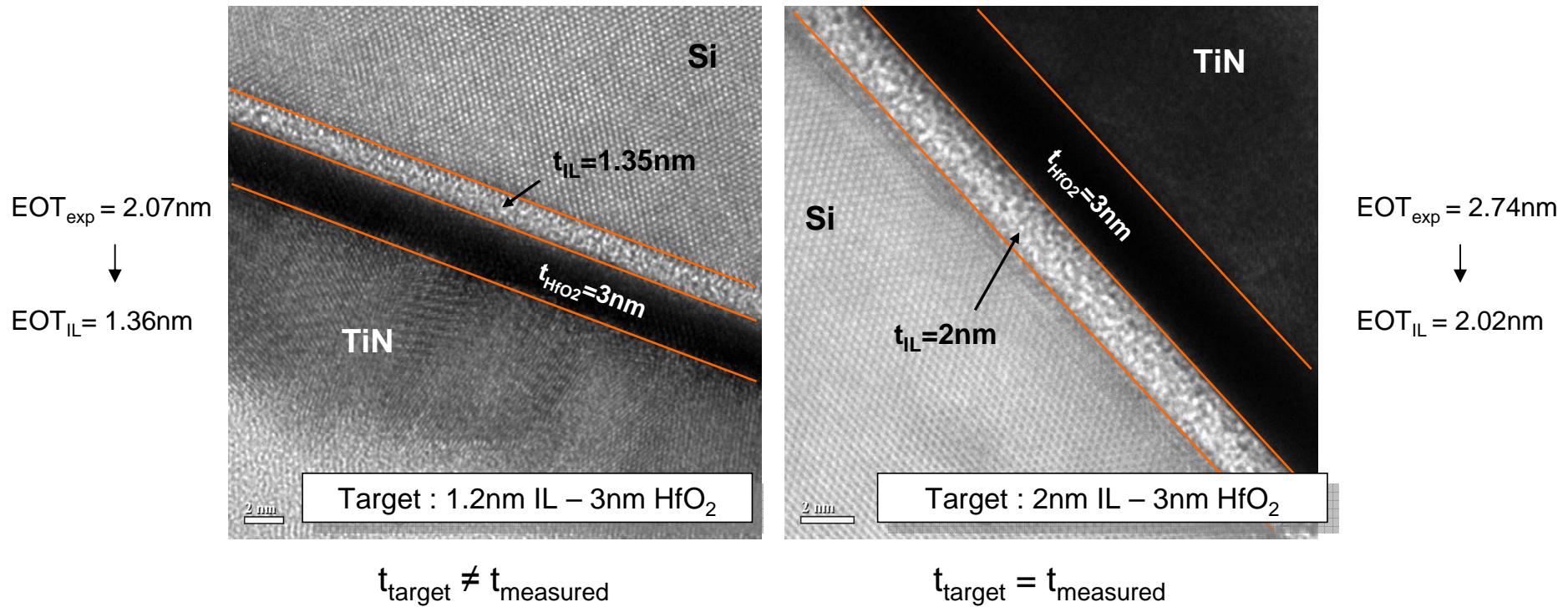
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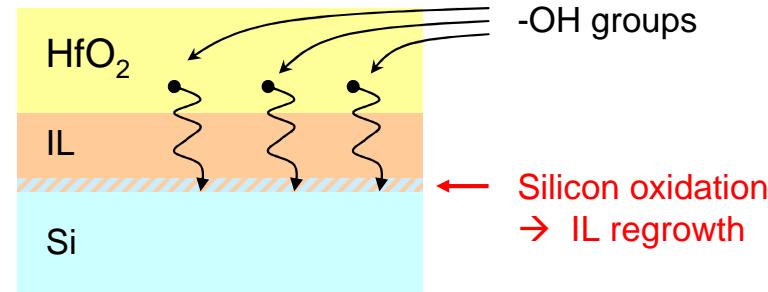
→ RTO IL devices : IL = SiO<sub>2</sub>

→  $\epsilon_{IL,RTO} = 3.9\epsilon_0$

Coignus et al., SSE '10

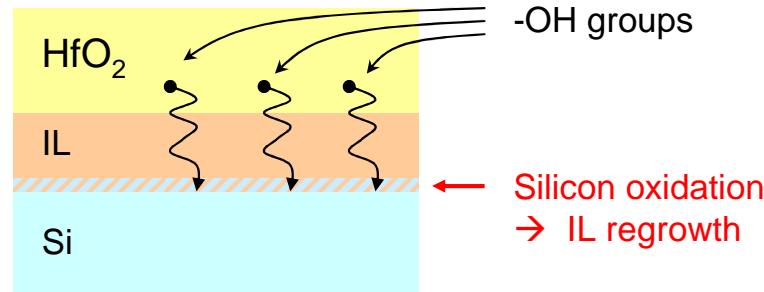
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[Damlencourt SSE '03]



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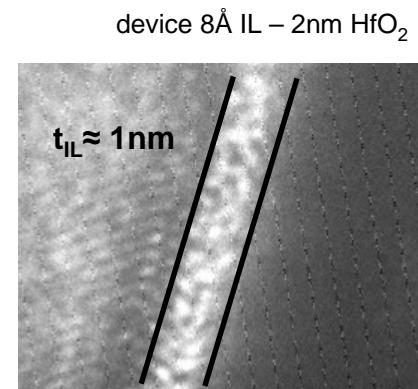
- TEM observations on chemical IL devices

→ target = 8Å   EOT<sub>IL,exp</sub> ≈ 6-7Å   TEM observation ≈ 1nm

→  $\epsilon_{IL,chem} > \epsilon_{SiO_2}$

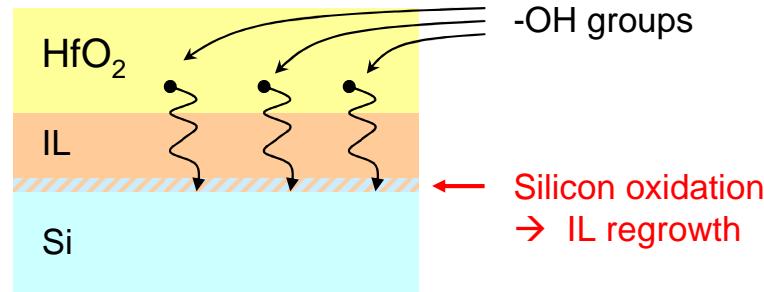
→ **Chemical IL devices :**

**IL = silicate or SiO<sub>x</sub>**



# Dielectric thicknesses extraction

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[Damlencourt SSE '03]



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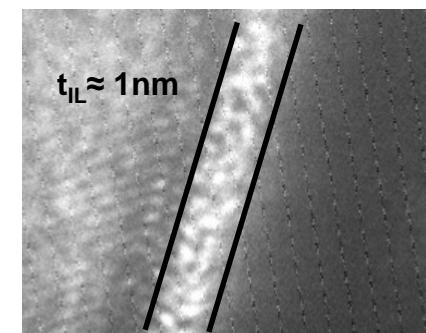
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→ **Chemical IL devices :**

**IL = silicate or SiO<sub>x</sub>**

device 8Å IL – 2nm HfO<sub>2</sub>



$$EOT_{exp} \rightarrow t_{phys}$$

# Outline

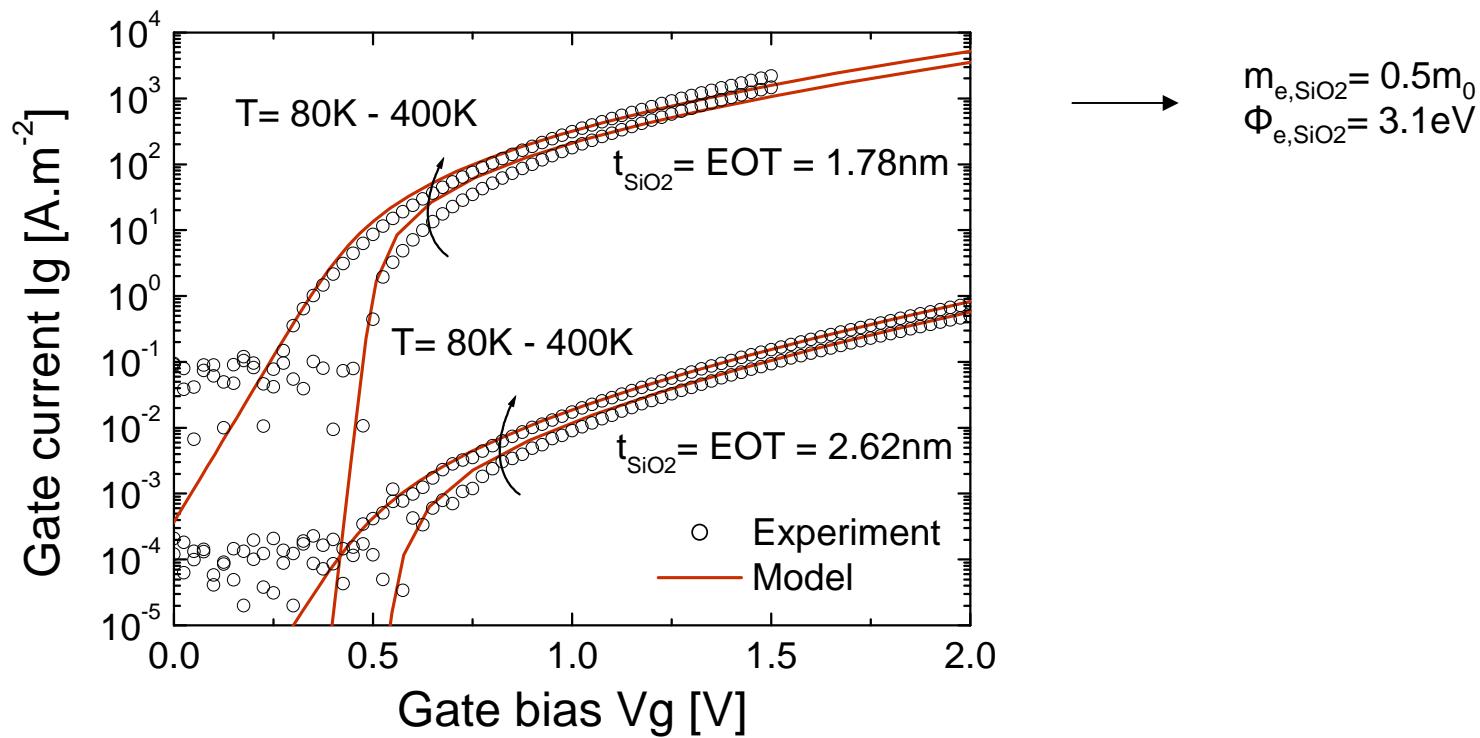
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- **Tunneling current modeling**
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  - Transmission probability
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- **Conclusions**

# Tunneling parameters extraction @80K

- **Inversion regime**

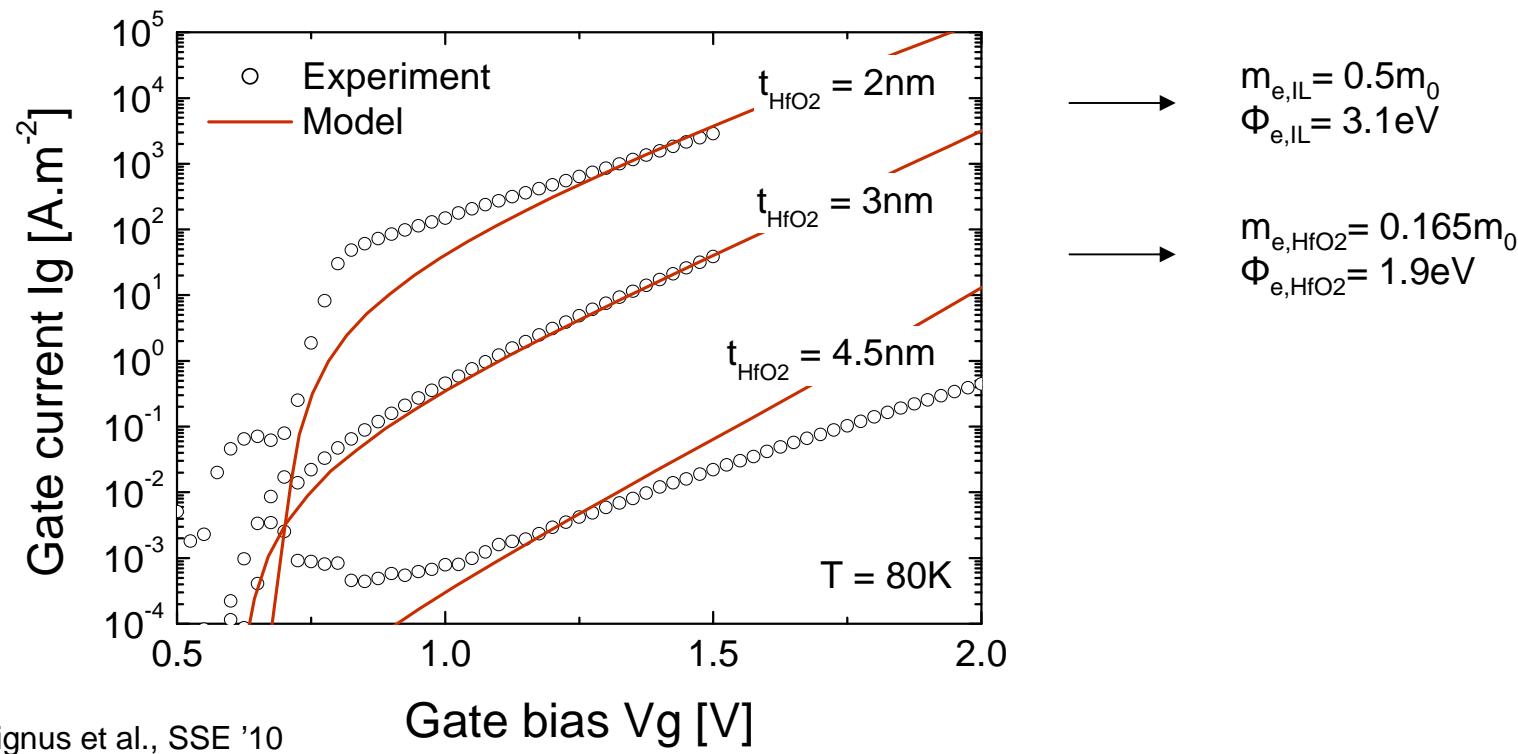
1.  $\text{SiO}_2$  – Polysilicon reference samples



# Tunneling parameters extraction @80K

- **Inversion regime**

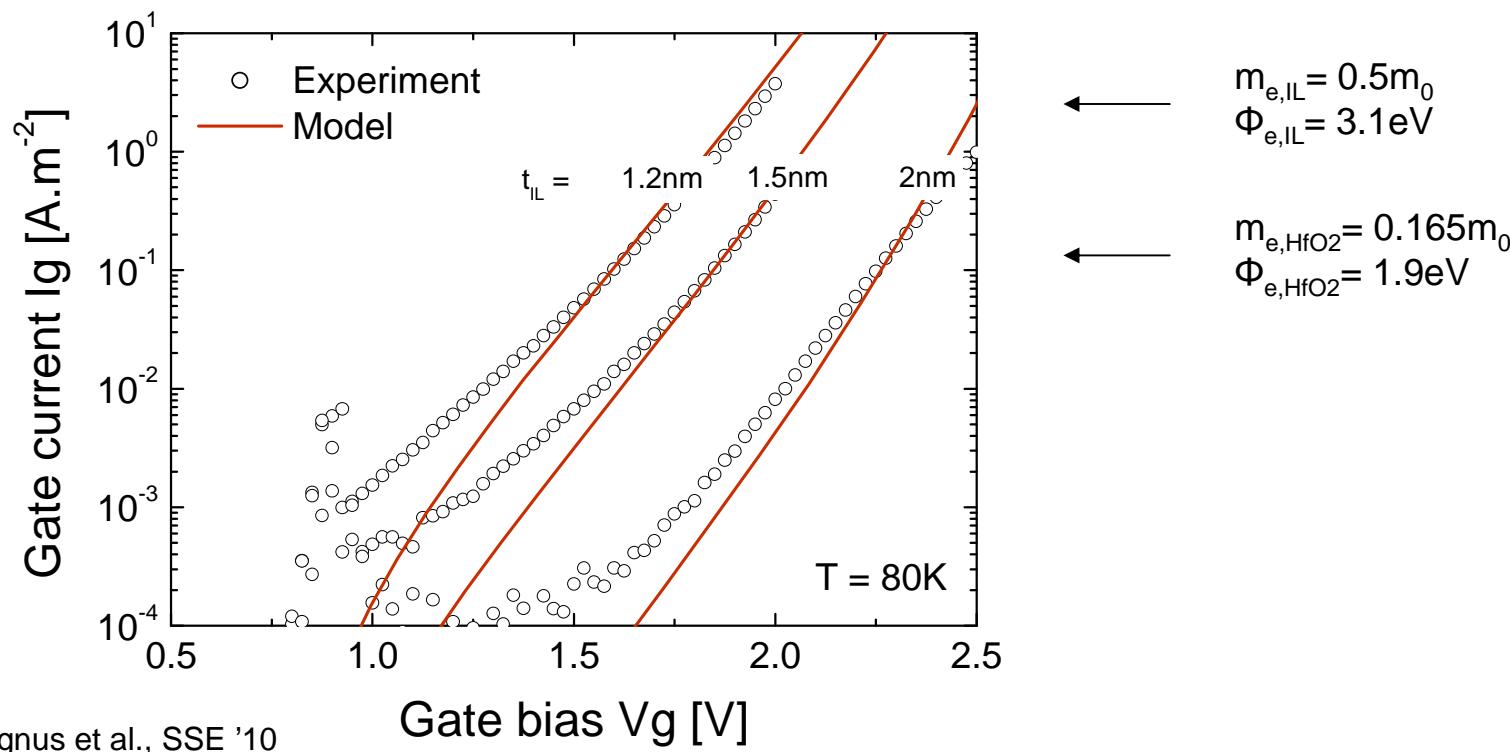
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# Tunneling parameters extraction @80K

- **Inversion regime**

1. SiO<sub>2</sub> – Polysilicon reference samples
2. HfO<sub>2</sub> gate stacks : HfO<sub>2</sub> thickness variants
3. HfO<sub>2</sub> gate stacks : IL thickness variants



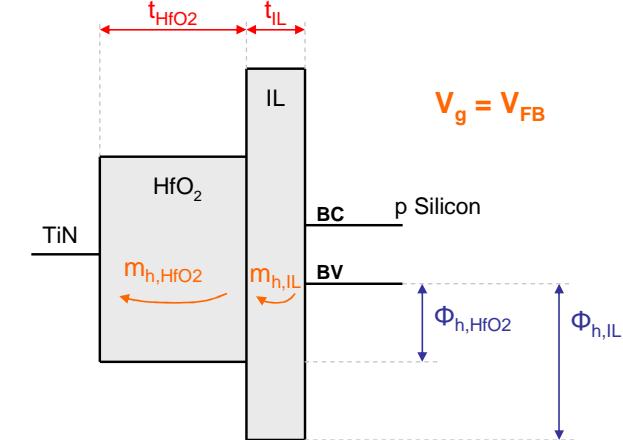
Coignus et al., SSE '10

# Tunneling parameters extraction @80K

- **Accumulation regime**

$\Phi_{h,IL} = 4.78\text{eV}$  and  $\Phi_{h,HfO_2} = 2.83\text{eV}$  obtained from experimental extraction of bandgap

Charbonnier, TED '10  
Martinez, ECS '09

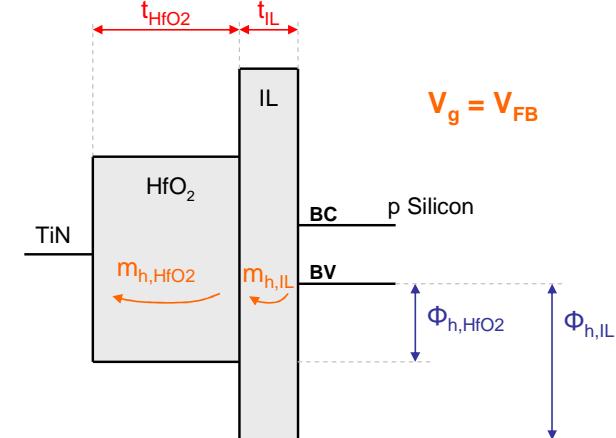


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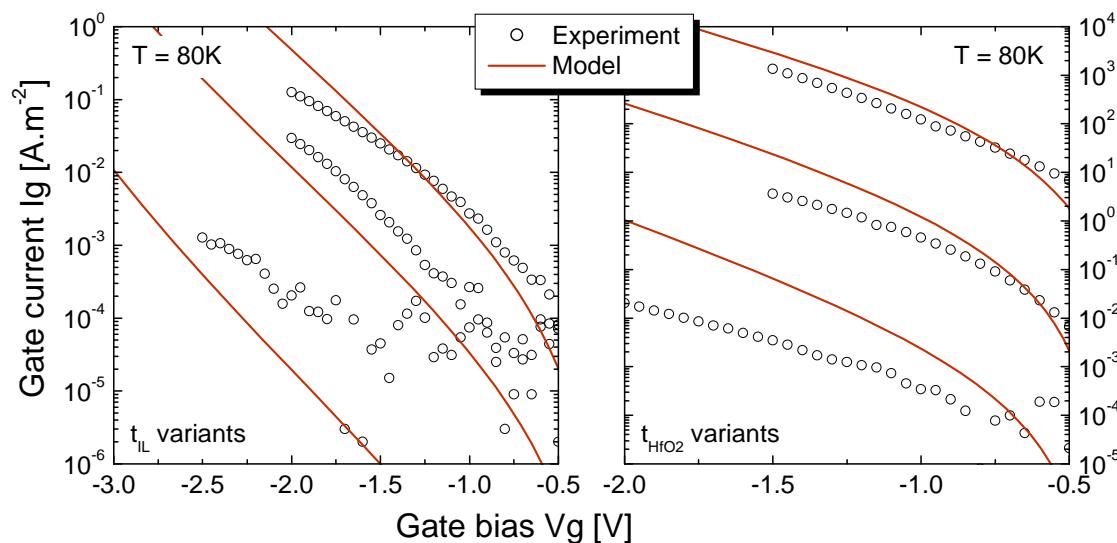
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Charbonnier, TED '10  
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- Best fit obtained :**

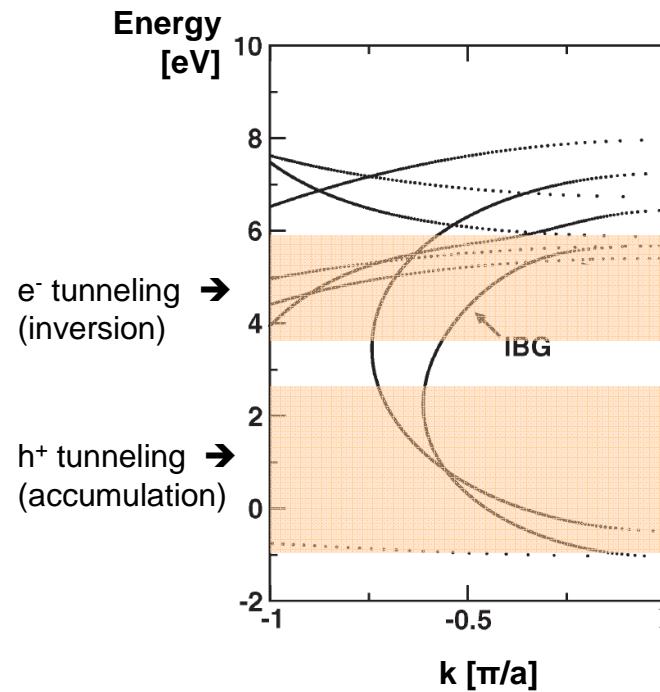


→ **2D tunneling model fails to reproduce experiment**

( $m_{h,IL}=0.5m_0$ ,  $m_{h,HfO_2}=0.06m_0$ ,  $\Phi_{h,IL}=4.78\text{eV}$ ,  $\Phi_{h,HfO_2}=2.83\text{eV}$ )

# Tunneling parameters extraction @80K

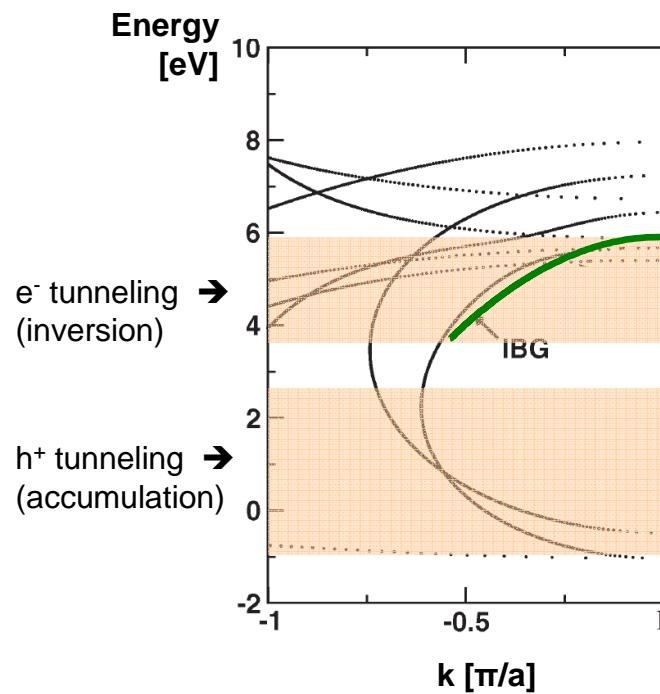
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Sacconi TED '07

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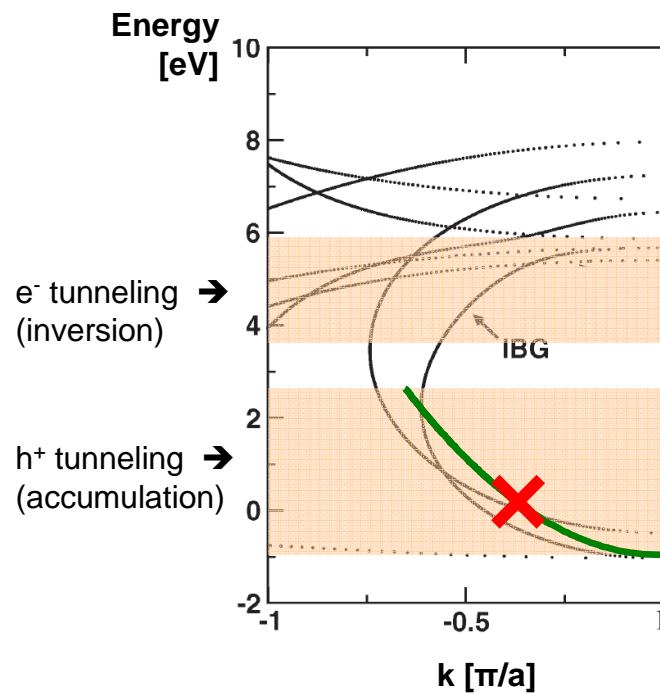


- Inversion regime :  
parabolic description with  $m_{\text{HfO}_2} = 0.165m_0$  **OK**

$$k_z(E) = \frac{1}{\hbar} \sqrt{2m_e E},$$

# Tunneling parameters extraction @80K

- This model assumes a parabolic description of IL and  $\text{HfO}_2$  band structure

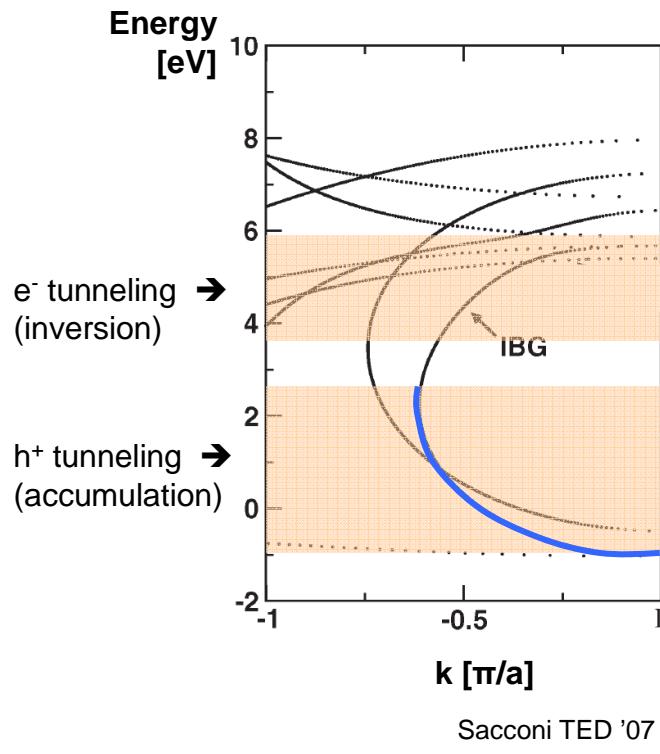


- Inversion regime :  
parabolic description with  $m_{\text{HfO}_2} = 0.165m_0$  **OK**
- Accumulation regime  
parabolic description fails to reproduce band structure  
→ new description needed

Sacconi TED '07

# Tunneling parameters extraction @80K

- This model assumes a parabolic description of IL and  $\text{HfO}_2$  band structure



- Inversion regime :  
parabolic description with  $m_{\text{HfO}_2} = 0.165m_0$  **OK**

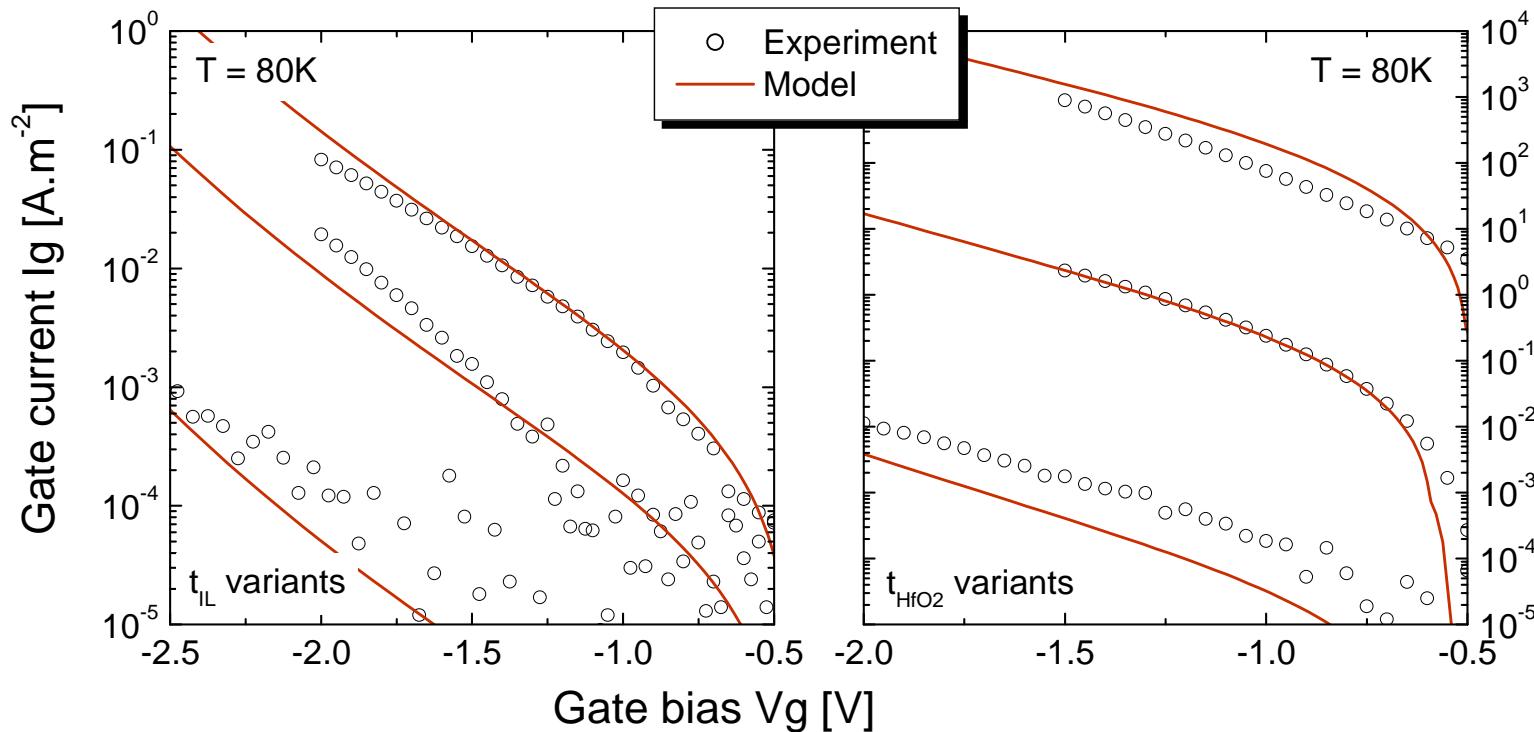
- Accumulation regime  
parabolic description fails to reproduce band structure  
→ new description needed

Franz-type description introduced (fitting parameter  $m_f$  : Franz-type tunneling mass)

$$k_z(E) = \frac{1}{\hbar} \sqrt{2m_f E \left(1 - \frac{E}{E_g}\right)}$$

# Tunneling parameters extraction @80K

- **Accumulation regime**



**Best fit obtained with :**

$$m_{f,IL} = 0.5m_0$$

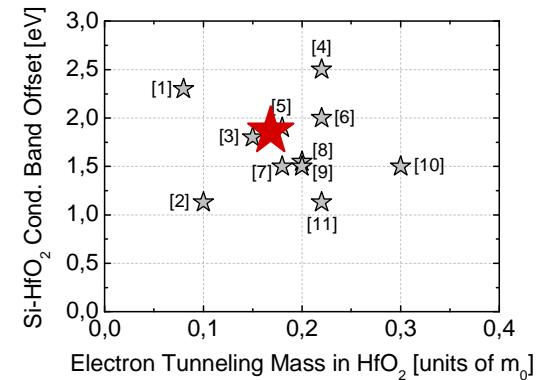
$$m_{f,HfO2} = 0.22m_0$$

$$\Phi_{h,IL} = 4.78\text{eV}$$

$$\Phi_{h,HfO2} = 2.83\text{eV}$$

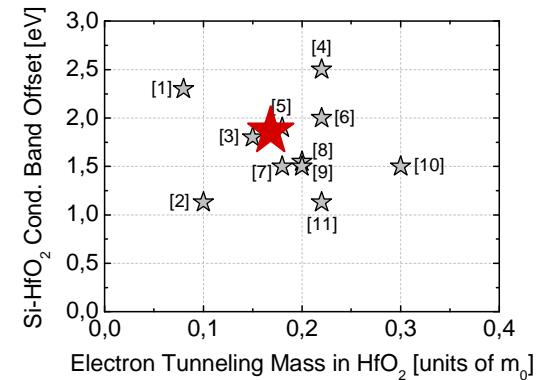
# Tunneling parameters extraction : conclusions

- **Issue 2** : One single set of tunneling parameters explains the **whole** set of experiments  
→ exception :  $t_{\text{HfO}_2} = 4.5\text{nm}$



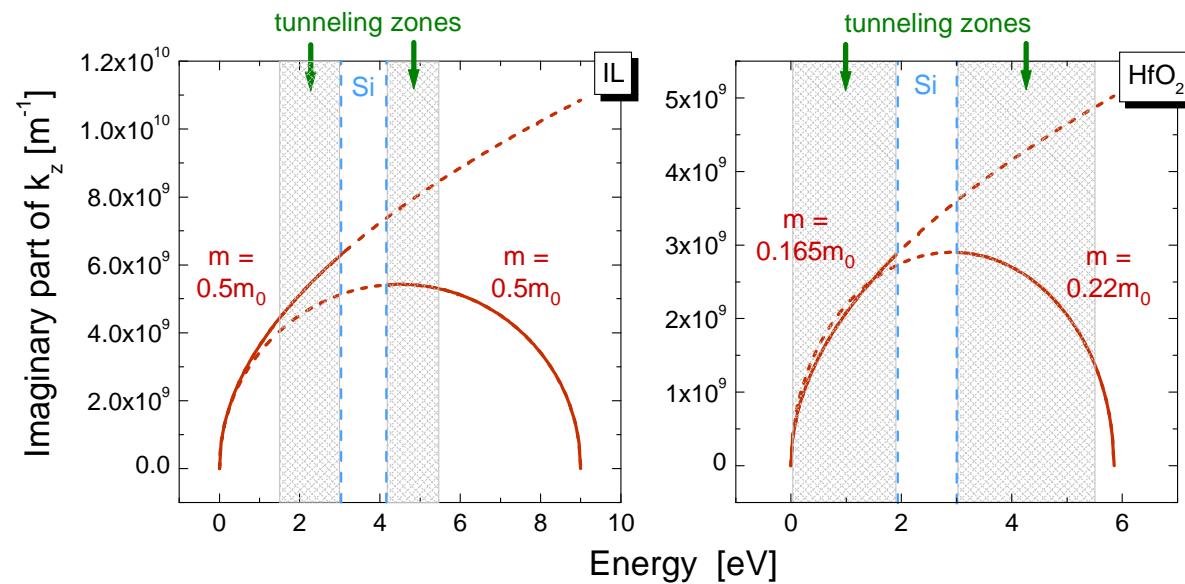
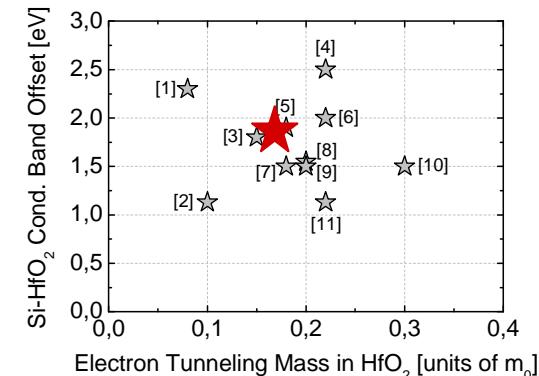
# Tunneling parameters extraction : conclusions

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→ exception :  $t_{\text{HfO}_2} = 4.5\text{nm}$
- Current @80K is a pure tunneling mechanism  
→ experiments @low T are mandatory for  $t_{\text{high-k}} > 2.5\text{nm}$



# Tunneling parameters extraction : conclusions

- **Issue 2** : One single set of tunneling parameters explains the **whole set** of experiments  
→ exception :  $t_{\text{HfO}_2} = 4.5\text{nm}$
- Current @80K is a pure tunneling mechanism  
→ experiments @low T are mandatory for  $t_{\text{high-k}} > 2.5\text{nm}$
- HfO<sub>2</sub> and IL band structures have been electricaly extracted



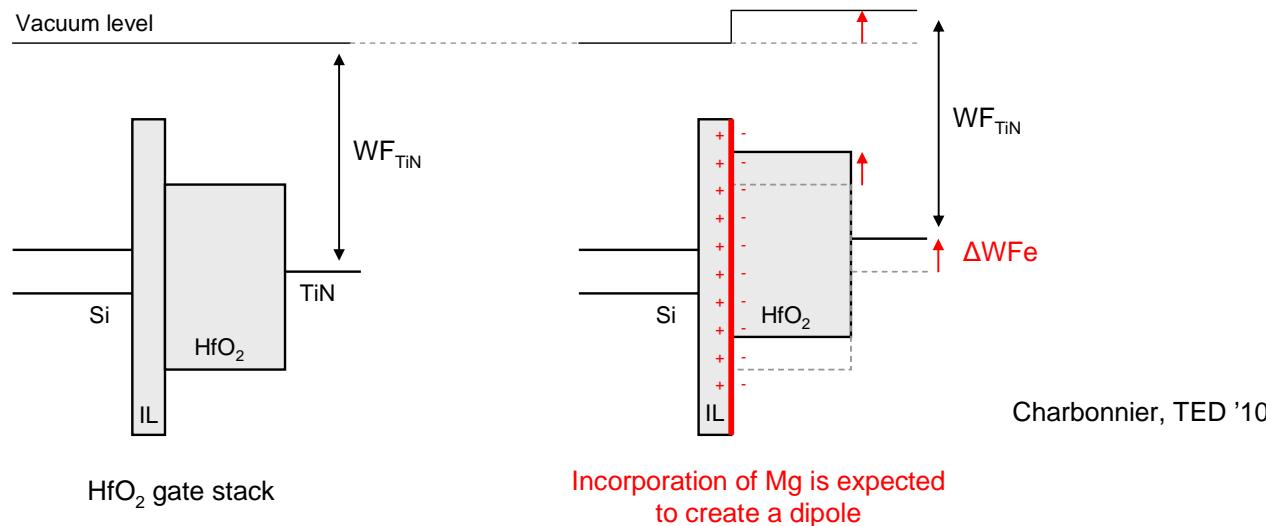
# Outline

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- **Tunneling current modeling**
  - Self-consistent Poisson-Schrödinger simulation
  - Transmission probability
- **Experimental investigation of leakage current in  $\text{HfO}_2$  gate stacks**
  - Transport mechanisms
  - Dielectric thicknesses extraction
  - Tunneling parameters extraction
  - Dipole effect in Mg-capped  $\text{HfO}_2$  gate stacks
- **Conclusions**

# Dipole effect in Mg-capped HfO<sub>2</sub> gate stacks

- $V_{TH}$ - tunning for 32nm HP devices

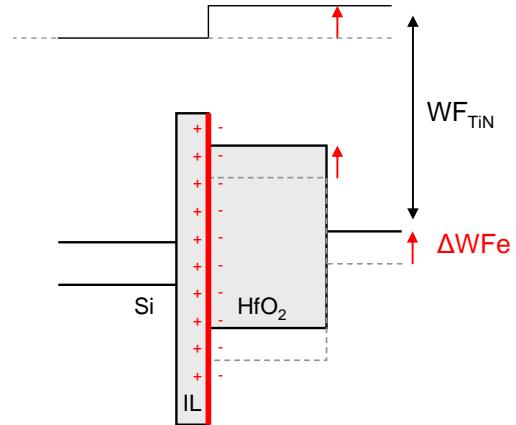
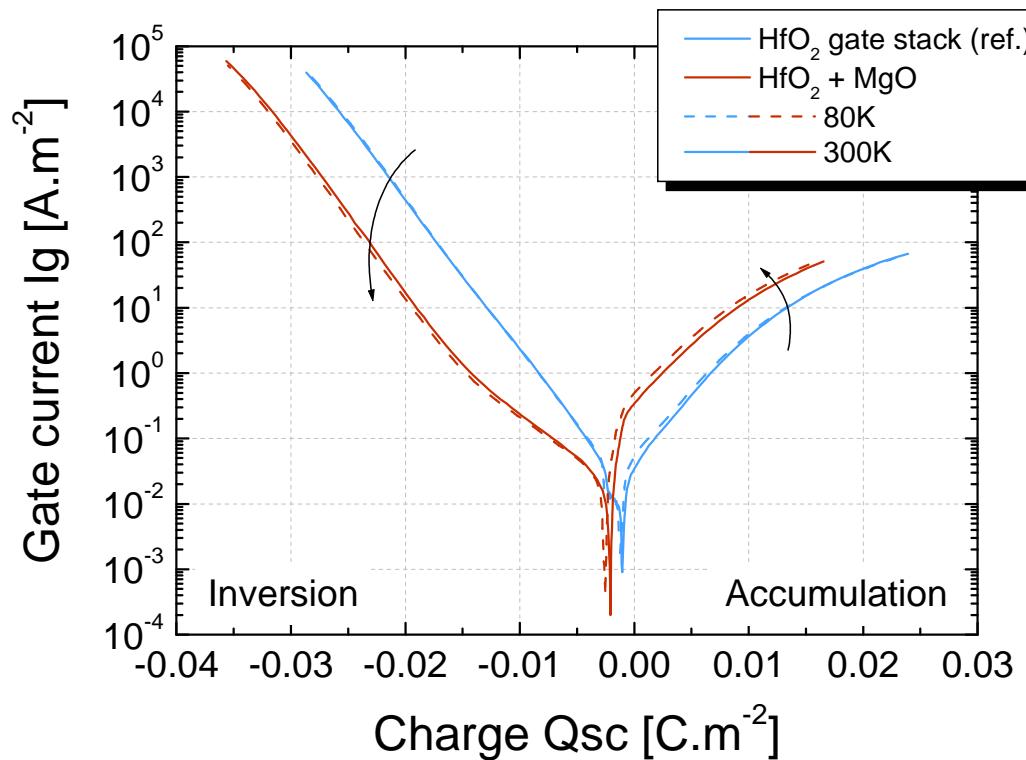


**$V_{fb}$  shift is usually observed**  
→ due to fixed charges ?  
→ due to dipole ?

➔ gate leakage study : investigation of barrier height shifts

# Dipole effect in Mg-capped HfO<sub>2</sub> gate stacks

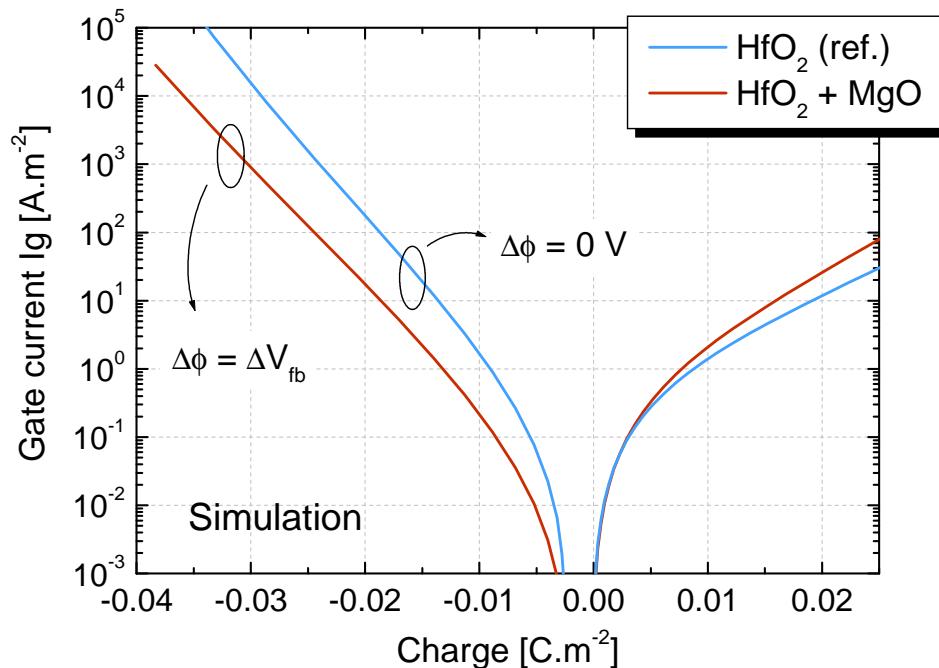
- Incorporation of 0.3nm MgO in standard HfO<sub>2</sub> gate stack



→ Coherent with barrier height shifts

# Dipole effect in Mg-capped HfO<sub>2</sub> gate stacks

- Simulation of HfO<sub>2</sub> ref. sample + Mg-capped gate stack



Tunneling parameters extraction suffer from uncertainties in gate stack materials

**Investigation of gate leakage appears mandatory for  $V_{fb}$  shift study in capped gate stacks.**

**Additional samples and measurements should be considered for accurate quantitative results.**

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# Conclusions

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- Gate leakage mechanisms in high-k gate stacks have been investigated, by mean of :
  - quantum models for tunneling and quantization simulation
    - Accounting for wavefunction penetration in PS simulation appears mandatory for ultra-thin gate stacks
    - Advanced VB description does not significantly impact EOT extraction
    - WKB formalism inaccuracy has been highlighted
    - An original approach for transmission probability modeling is proposed
  - a complete experimental study performed
    - @ low temperature (transport mechanisms discrimination)
    - on various high-k gate stacks (dielectrics parameters evaluation)

# Conclusions

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- Transport mechanisms in  $\text{HfO}_2$ 
  - In inversion :
    - Direct tunneling for thin layers ( $<2.5\text{nm}$ , eg.  $32\text{nm}$  node)
    - Poole Frenkel or inelastic TAT for thick  $\text{HfO}_2$  layers ( $>2.5\text{nm}$ ) (@80K : tunneling)
  - In accumulation : pure tunneling
- IL parameters have been shown to differ from target values
  - RTO IL : regrowth
  - Chemical IL : silicate or substoechiometry
- Effective Mass Approximation in dielectrics :
  - **OK** for electrons
  - **Not valid** for holes : Franz-type E-k
- Carefull experimental study allowed to reach a better consensus on  $\text{HfO}_2$  band structure and tunneling parameters

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Thank you for your attention